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CUSTOMER'S CODE PAN13XX Core Specification	PANASONIC'S CO See Chapter Orderin		DATE	08.11.20)17			
Product Specification								
Manufacturer	Panasonic Ir Zeppelinstra 21337 Lünek Germany		Europe GmbH					
By purchase of any the document's vali contents and recom required at any time Product Specificatio	dity and declares th mendations. Panas without notification	eir agreement ar conic reserves the . Please consult	nd understanding e right to make o the most recent	g of its hanges	as			
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All rights reserved.								
This Product Specif mistakes.	fication does not loc	lge the claim to b	e complete and	free of				
Power Electronics Ra Wireless Conne		APPROVED	CHECKED	DESI	IGNED			
Panasonic Industrial Device								

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1 ABOUT THIS DOCUMENT

1.1 PURPOSE

This product specification describes Panasonic's HCI, Class 1.5 , TI based, Bluetooth ${}^{\!\!\rm B}^1$ modules, series number 13xx.

For detailed family overview that includes part numbers see Chapter 29, Ordering Information.

Non-antenna versions will be referred to as PAN131x, versions with antenna will be referred to as PAN132x in this document.

For information and features on Bluetooth Low Energy 4.0 refer to Chapter 21, for information on ANT refer to Chapter 23.

1.2 REVISION HISTORY

Revision	Date	Modification / Remarks
1.00	04.11.2010	1 st internal Release.
1.01	03.12.2010	Included reference to PAN1325 Application Note. AN-1325-2420-111.pdf.
1.02	10.01.2011	Changed wording in Chapter 31.2 "Industry Canada Certification".
1.03	23.05.2011	Included DOC for PAN1315 series. Included PAN13xx ANT and BLE Addendum Rev1.x.pdf reference. Included Note for IO voltage and MLD_OUT pin.
1.04	02.07.2011	Corrected wording in Chapter 31.3 European Conformity.
1.05	28.10.2011	Including CC2560A silicon PAN1315A HW40 at Chapter 2, Chapter New PAN13x5 and Chapter 0. Deleted ES label in Chapter.
1.06	15.11.2011	Added overview for the core specification and their addendums. Updated front page. Updated Related Documents.
3.00	11.01.2012	Merging PAN13xx documents into this specification and correct some format.
3.10	16.01.2012	Minor mistakes fixed.
3.20	29.05.2012	DoC replaced with revised version.
3.30	11.06.2012	Added triple mode stack Module PAN1323, add PAN1323 to ordering and software information overview, Software Block Diagram added, Bluetooth Inter IC-Sound chapter information added Layout Recommandations with Antenna added, Application Note LGA added
3.31	27.06.2012	Added design information to use low pass filter (chapter 11.1 / 11.9) for better noise surpression when using PCM interface.
3.40	18.07.2012	Re-organize chapter Regulatory Information and added 2 chapters.
3.50	31.10.2012	Changed the Overview in chapter Ordering Information Included -40°C to 85°C Version ENW898xxA2 <u>K</u> F. So called K-Version.
3.60	17.05.2013	Changed FCC-ID for models ENW89823xxx and ENW89827xxx.
3.70	31.05.2013	DoC replaced with revised version, updated links.
3.71	15.08.2013	Added component values for low pass filter on PCM interface.
3.80	11.11.2013	Changed CC2567 to CC2564 in chapter ordering information.
3.90	03.12.2013	Included CC2560/4B PAN1325/6B in chapter 2.

¹ Bluetooth is a registered trademark of the Bluetooth Special Interest Group.

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Revision	Date	Modification / Remarks
4.00	19.12.2013	Updated chapter European Conformity.
4.10	10.01.2014	Added chapter 20 Radiation Pattern.
4.20	28.02.2014	Changed chapter Key Features according to EN regulations.
4.3	24.09.2014	Added chapter 27.
4.4	06.11.2014	Added DoC.
4.5	29.04.2015	Removed chapter 27 and updated chapter 8 Block Diagram.
4.6	07.05.2015	Removed Taiwan Regulatory chapter.
4.61	19.05.2015	Deleted Chapter 2.1 Software Blockdiagram.
4.7	11.06.2015	Changed the wording in chapter 8 Block Diagram.
4.8	23.09.2015	Added Japanese radio law requirements for labeling.
4.9	09.03.2017	Added CC2564C in the product description. Added new partnumber.
5.0	14.06.2017	Editorial changes. Added RED declaration. Added Korean certification chapter.
5.1	08.11.2017	Removed PAN13x6C Version => moved to separate product specification

1.3 RELATED DOCUMENTS

For an update, please refer to the the respective homepage.

- [1] PAN1323ETU Design-Guide: http://www.panasonic.com/industrial/includes/pdf/PAN1323ETUDesignGuide.pdf
- [2] CC2560 Product Bulletin: <u>http://focus.ti.com/pdfs/wtbu/cc2560_slyt377.pdf</u>
- [3] Bluetooth SW for MSP430 is supported by IAR IDE service pack 5.10.6 and later. Use full IAR version edition (not the kick-start version). You can find info on IAR at http://www.iar.com/website1/1.0.1.0/3/1/ and www.MSP430.com. Note, that there is an option for a 30-day free version of IAR evaluation edition.
- [4] PAN13xx CAD data: <u>http://www.pedeu.panasonic.de/pdf/174ext.zip</u>
- [5] To help with the implementation of this reference design, Eagle formatted application and layout files are available on the web at the address below.
- [6] www.panasonic.com/industrial/includes/pdf/PAN1323ETU_Eagle_Ver1_1.zip
- [7] Application Note Land Grid Array: http://www.pedeu.panasonic.de/pdf/184ext.pdf

1.4 GENERAL INFORMATION

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Engineering Samples (ES)

If Engineering Samples are delivered to the customer, these samples have the status "Engineering Samples". This means that the design of this product is not yet concluded. Engineering Samples may be partially or fully functional, and they may differ from the published Product Specification.

Engineering Samples are not qualified and they are not to be used for reliability testing or series production.

Disclaimer

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- Deviation or lapse in function of the Engineering Sample,
- Improper use of the Engineering Sample.

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1.5 CONTACT US

Please contact your local Panasonic Sales office for details on additional product options and services:

For Panasonic Sales assistance in the EU, visit

https://eu.industrial.panasonic.com/about-us/contact-us

Email: wireless@eu.panasonic.com

For Panasonic Sales assistance in **North America**, visit the Panasonic Sales & Support Tool to find assistance near you at

https://na.industrial.panasonic.com/distributors

Please visit the Panasonic Wireless Technical Forum to submit a question at

https://forum.na.industrial.panasonic.com

Please refer to the Panasonic Wireless Connectivity website for further information on our products and related documents:

For complete Panasonic product details in the EU, visit

http://pideu.panasonic.de/products/wireless-modules.html

For complete Panasonic product details in North America, visit

http://www.panasonic.com/rfmodules

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2 NEW PAN13X5B, PAN13X6B

The PAN13x5B and PAN13x6B Series are based on Texas Instruments CC2560B and CC2564B controller respectively. The PAN13x5B/13x6B Series Modules support assisted mode for the HFP1.6 (WBS) profile or the A2DP profile. The PAN13x6B also supports 10 LE connections (instead of 6 before).

Compatibility:

PAN1315(A/B) and PAN1316(B) are 100% footprint compatible

PAN1325(A/B) and PAN1326(B) are 100% footprint compatible

NOTE: In the following chapters PAN13x5, PAN13x6 naming also considers the A and B version.

As an updated initialization script resident on the application microcontroller is required for modules based on the CC2560A and CC2564A/B, compatibility between the basic, A and B version is dependent on the Bluetooth stack.

BT-Stack solutions provided by software development partners are available for most processors, including linux based host systems.

For detailed family overview that includes part numbers see Chapter 29 Ordering Information.

Contact your stack provider or local Panasonic sales company for currently available Bluetooth Profiles.

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CUSTOMER'S CODE PAN13XX Core Specification	PANASONIC'S CODE See Chapter Ordering Informatio	n DATE	08.11.20)17
 Surface mount type 6.5 Up to 10 dBm Tx power High sensitivity (-93 dBi Texas Instrument's CC2 Fast Connection Setup Extended SCO Link Supports convenient dir or connect to DC/DC (1 Internal crystal oscillato Fully shielded for immu Full Bluetooth data rate Support for Bluetooth provide the support for very low-po Optional support for ultr PCM Interface Master of CVSD transcoders on u Full 8- to 128-bit encryp UART, I²C and PCM Int IO operating voltage = 7 Bluetooth profiles such module website for a lis Manufactured in conform 	256X BlueLink 7.0 inside rect connection to battery (2.2-4.8 .7-1.98 V) for improved power effir r (26MHz) nity up to 2,178kbps asymmetric ower saving modes (Sniff, Hold) wer modes (deep sleep and powe a-low-power mode. Standby with 1 ' Slave supporting 13 or 16 bit lin p to 3 SCO channels tion erface 1.8 V nominal as SPP, A2DP and others are ting of the most current releases. mance with RoHS	V), ciency r down) Battery-Backup ear, 8 bit μ-law or A-law		
4 APPLICATIONS FOR				
All Embedded Wireless Smart Phones Industrial Contro	Cable F	eplacement tive		

- Medical •
- Scanners •
- Wireless Sensors •
- Low Power •

- Access Points •
- **Consumer Electronics** •
- Monitoring and Control •
- Access Points •

SUBJECT CLASS 1 or 2 BLUETOOTH MODULE PAGE 9 of 55 CUSTOMER'S CODE PANASONIC'S CODE DATE 00.14 0047	CLASSIFICATION	PRODUCT SPE	CIFICATION	No. DS-13xx-2400-	102	REV. 5.1
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5 DESCRIPTION FOR THE MODULE

The PAN1315 and PAN1315A are short-range, Class 1 or 2, HCI modules for implementing Bluetooth functionality into various electronic devices. A block diagram can be found in Chapter 8.

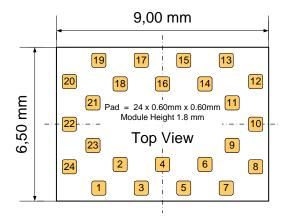
Communication between the module and the host controller is carried out via UART.

New designs can be completed quickly by mating the PAN13xx series modules with Texas Instruments' MSP430BT5190 that contains Mindtree's EtherMind Bluetooth Protocol Stack and serial port profile, additional computing power can be achieved by choosing TI's Stellaris ARM7 controller that includes StoneStreet One's A2DP profile. Other BT profiles are available on custom development basis.

Additional controllers are also supported by the PAN13xx series by using a TI/Panasonic software development partner to port the Bluetooth stack and profiles. Mindtree's Software Development Kit (SDK) is available on TI's website -- www.ti.com/connectivity.com

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6 DETAILED DESCRIPTION					
6.1 TERMINAL	LAYOUT				

6.1.1 Terminal Layout PAN131x without antenna

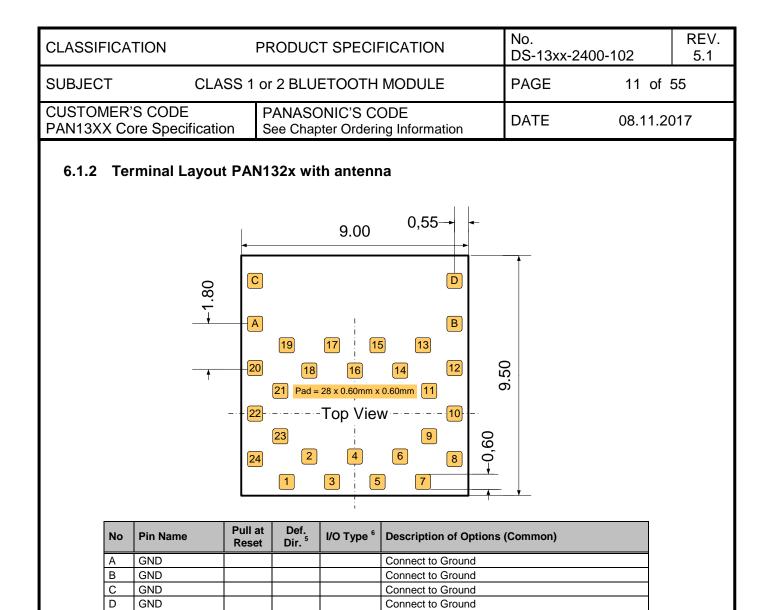


No	Pin Name	Pull at Reset	Def. Dir. ²	I/O Type ³	Description of Options (Common)	
1	GND				Connect to Ground	
2	TX_DBG	PU	0	2 mA	Logger output	
3	HCI_CTS	PU	1	8 mA	HCI UART clear-to-send.	
4	HCI_RTS	PU	0	8 mA	HCI UART request-to-send.	
5	HCI_RX	PU	1	8 mA	HCI UART data receive	
6	HCI_TX	PU	0	8 mA	HCI UART data transmit	
7	AUD_FSYNC	PD	10	4 mA	PCM frame synch. (NC if not used)	Fail safe ⁴
8	SLOW_CLK_IN		1		32.768-kHz clock in	Fail safe
9	NC		10		Not connected	
10	MLDO_OUT		0		Main LDO output (1.8 V nom.)	
11	CL1.5_LDO_IN		I		PA LDO input	
12	GND				Connect to Ground	
13	RF		10		Bluetooth RF IO	
14	GND				Connect to Ground	
15	MLDO_IN		1		Main LDO input	
16	nSHUTD	PD	1		Shutdown input (active low).	
17	AUD_OUT	PD	0	4 mA	PCM data output. (NC if not used)	Fail safe
18	AUD_IN	PD	1	4 mA	PCM data input. (NC if not used)	Fail safe
19	AUD_CLK	PD	10	HY, 4 mA	PCM clock. (NC if not used)	Fail safe
20	GND				Connect to Ground	
21	NC				EEPROM I ² C SDA (Internal)	
22	VDD_IO		PI		I/O power supply 1.8 V Nom	
23	NC				EEPROM I ² C SCL (Internal)	
24	NC		10		Not connected	

^{2} I = input; O = output; IO = bidirectional; P = power; PU = pulled up; PD = pulled down

³ I/O Type: Digital I/O cells. HY = input hysteresis, current = typ. output current

⁴ No signals are allowed on the IO pins if no VDD_IO (Pin 22) power supplied, except pin 7, 8, 17-19.



No 1-24 see above in Chapter 6.1.1. Except PIN 13 is not connected. For RF conducted measurements, either use the PAN1323ETU or de-solder the antenna and solder an antenna connector to the hot pin.

6.2 PIN DESCRIPTION

Pin Name	No	ESD ⁷ (V)	Pull at Reset	Def. Dir. ⁸	I/O Type ⁹	Description of Options
					Bluetooth IC	D SIGNALS
HCI_RX	5	750	PU	I	8 mA	HCI UART data receive

⁵ I = input; O = output; IO = bidirectional; P = power; PU = pulled up; PD = pulled down

⁶ I/O Type: Digital I/O cells. HY = input hysteresis, current = typ. output current

⁷ ESD: Human Body Model (HBM). JEDEC 22-A114

⁸ I = input; O = output; IO = bidirectional; P = power; PU = pulled up; PD = pulled down

⁹ I/O Type: Digital I/O cells. HY = input hysteresis, current = typ output current

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CUSTOMER'S CODE PAN13XX Core Specif		ion	-		S CODE		DATE	08.11.20)17
Pin Name	No	ESD ⁷ (V)	Pull at Reset	Def. Dir. ⁸	I/O Type ⁹	Description of Opt	tions		
HCI_TX	6	750	PU	0	8 mA	HCI UART data tr	ransmit		
HCI_RTS	4	750	PU	0	8 mA	HCI UART reques	st-to-send.		
HCI_CTS	3	750	PU	I	8 mA	HCI UART clear-t	to-send.		
AUD_FYSNC	7	500	PD	10	4 mA		h (NC if not used)	Fail safe	
AUD_CLK	19	500	PD	IO	HY, 4 mS	PCM clock	(NC if not used)	Fail safe	
AUD_IN	18	500	PD	1	4 mA	PCM data input	(NC if not used)	Fail safe	
AUD_OUT	17	500	PD	0	4 mA	PCM data output	(NC if not used)	Fail safe	
TX_DBG	2	1000	PU	0	2 mA		BG – logger out (low :	1)	
					CLOCK	SIGNALS		= 1)	
SLOW_CLK_IN	8	1000	1	Ti		32.768-kHz clock	in	Fail safe	
		1000		B	duetooth AN/	ALOG SIGNALS		T di Salo	
RF	13	1000	T	10			(not connected with a	ntenna)	
nSHUTD	16	1000	PD		+	Shutdown input (a	(Interney	
	110	1000		Blueto	oth POWER	AND GND SIGNALS			
VDD_IO	22	1000	T	PI		I/O power supply			
				+	+	Main LDO input	1.0 V Non.		
MLDO_IN	15	1000		I		Connect directly to	to battery or to a pre-		
MLDO_OUT	10	1000		0		Main LDO output	(1.8 V nom.) Can not nnection to the RF pa	t be used as 1.8	
CL1.5_LDO_IN	11	1000		I		PA LDO input	to battery or to a pre-i		/ supply
GND	1	+		Р		Connect to Groun		0.3	
GND	12	1		P	1	Connect to Groun			
GND	14	+		P		Connect to Groun			
GND	20	1		P		Connect to Groun			
		E	EPROM IO	SIGNAL	S (EEPROM	I is optional in PAN1			
NC	23	1000	PU/PD	I	HY, 4mA	EEPROM I ² C SCI			
NC	21	1000	PU/PD	ю	HY, 4mA	EEPROM I ² C IRC	ג (Internal)		

Remark:

HCI_CTS is an input signal to the CC256X device:

- When HCI_CTS is low, then CC256X is allowed to send data to Host device.
- When HCI_CTS is high, then CC256X is not allowed to send data to Host device.

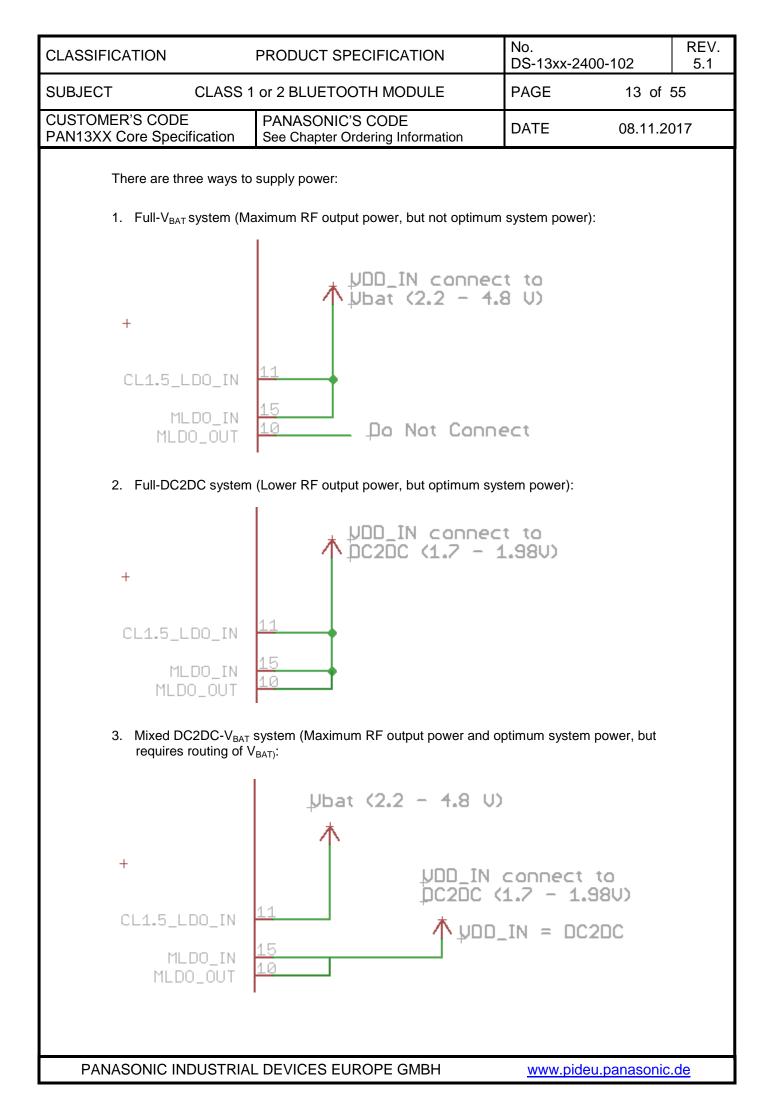
6.3 DEVICE POWER SUPPLY

The PAN13XX Bluetooth radio solution is intended to work in devices with a limited power budget such as cellular phones, headsets, hand-held PC's and other battery-operated devices. One of the main differentiators of the PAN13XX is its power management – its ability to draw as little current as possible.

The PAN13XX device requires two kinds of power sources:

- 1. Main power supply for the Bluetooth $VDD_IN = V_{BAT}$
- 2. Power source for the 1.8 V I/O ring VDD_IO

The PAN13XX includes several on-chip voltage regulators for increased noise immunity. The PAN13XX can be connected either directly to the battery or to an external 1.8-V DC to DC converter.



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6.4 CLOCK INPUTS

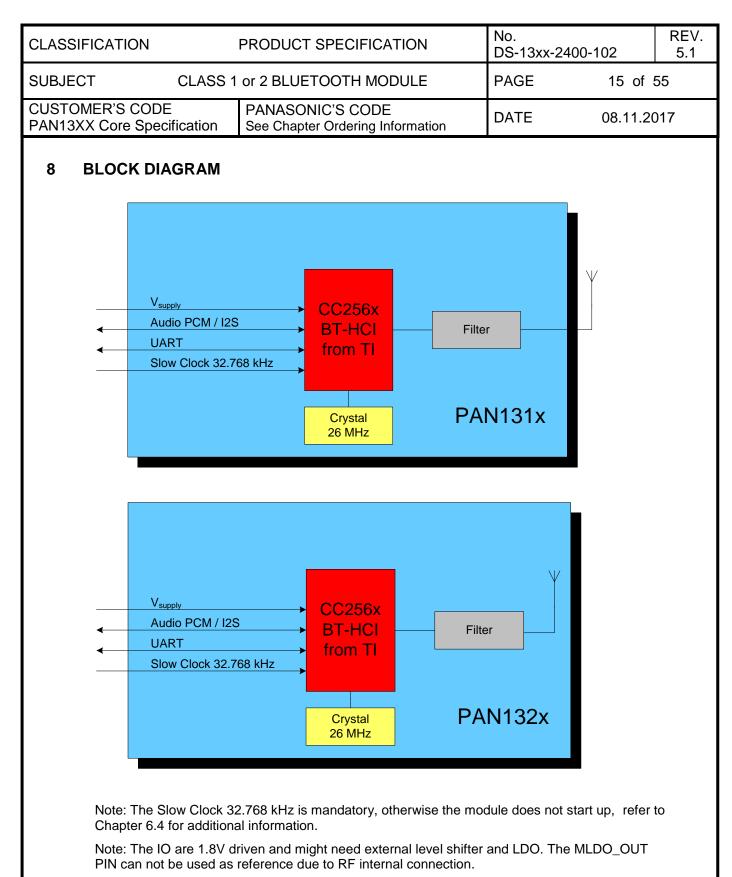
The slow clock is always supplied from an external source. It is connected to the SLOW_CLK_IN pin number 8 and can be a digital signal with peak to peak of 0-1.8 V.

The slow clock's frequency accuracy must be 32.768 kHz ± 250 ppm for Bluetooth usage (according to the Bluetooth specification).

The Slow Clock 32.768 kHz is mandatory to start the internal controller, otherwise the module does not start up.

7 BLUETOOTH FEATURES

- Support of Bluetooth2.1+EDR (Lisbon Release) up to HCI level.
- Very fast AFH algorithm for both ACL and eSCO.
- Supports typically 4 dBm Class 2 TX power w/o external PA, improving Bluetooth link robustness. Adjusting the host settings, the TX power can be increased to 10 dBm. However it is important, that the national regulations and Bluetooth specification are met.
- Digital Radio Processor (DRP) single-ended 50 ohm.
- Internal temperature detection and compensation ensures minimal variation in the RF performance over temperature.
- Flexible PCM and I2S digital audio/voice interfaces: Full flexibility of data-format (Linear, a-Law, μ-Law), data-width, data order, sampling and slot positioning, master/slave modes, high clock rates up to 15 MHz for slave mode (or 4.096 MHz for Master Mode). Lost packet concealment for improved audio.
- Proprietary low-power scan method for page and inquiry scans, achieves page and inquiry scans at 1/3rd normal power.



The total capacity will not exceed 2.8uF and the total inductance will not exceed 0nH. There are no voltage multiplying or voltage boosting circuits.

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9 TE		ONS			
ſ	Measurements sl	nall be made under room temperature and	humidity unless ot	herwise specifie	d.
10 G	ENERAL DEV	ICE REQUIREMENTS AND OPE	RATION		
	Temperature Humidity SW-Patch Supply Voltage	25 ± 10°C 40 to 85%RH V2.30 3.3V			
		are over temperature and process, unless	s indicated otherwise	e.	
10.1 A		XIMUM RATINGS			
(Over operating fr	ee-air temperature range (unless otherwis	se noted).		
(Over operating fro		se noted).		
(Over operating fr	Note			
ſ	Over operating fr	Note All parameters are measured as follows		rwise:	
Ĭ	Over operating fro	Note		rwise:	
ſ		Note All parameters are measured as follows	s unless stated othe		
	No See ¹¹	Note All parameters are measured as follows			
	No See ¹¹	Note All parameters are measured as follows $VDD_IN^{10} = 3.3 V, VDD_IO = 1.8 V.$	s unless stated othe		
	No See ¹¹ Ratings Over Operat	Note All parameters are measured as follows $VDD_IN^{10} = 3.3 \text{ V}, VDD_IO = 1.8 \text{ V}.$	s unless stated othe	e Unit	
	No See ¹¹ Ratings Over Operation 1 VDD_IN	Note All parameters are measured as follows VDD_IN ¹⁰ = 3.3 V, VDD_IO = 1.8 V.	s unless stated othe Valu	e Unit to 5.5 V ¹²	
	No See ¹¹ Ratings Over Operation 1 VDD_IN 2 2 VDDIO_1.8V 3 Input voltage to	Note All parameters are measured as follows VDD_IN ¹⁰ = 3.3 V, VDD_IO = 1.8 V.	s unless stated othe Value -0.5 -0.5 -0.5	e Unit to 5.5 V ¹² to 2.145 V	
	No See ¹¹ Ratings Over Operation 1 VDD_IN 2 2 VDDIO_1.8V 3 Input voltage to	Note All parameters are measured as follows VDD_IN ¹⁰ = 3.3 V, VDD_IO = 1.8 V. ing Free-Air Temperature Range Supply voltage range RF (Pin 13) tent temperature range	s unless stated othe Valu -0.5 -0.5 -0.5 -0.5 -40	e Unit to 5.5 V ¹² to 2.145 V to 2.1 V	
	No See ¹¹ Ratings Over Operation 1 VDD_IN 2 VDDIO_1.8V 3 Input voltage to 4 Operating amb	Note All parameters are measured as follows $VDD_IN^{10} = 3.3 \text{ V}, VDD_IO = 1.8 \text{ V}.$ ing Free-Air Temperature Range Supply voltage range RF (Pin 13) tent temperature range rature range	s unless stated othe Valu -0.5 -0.5 -0.5 -0.5 -40	e Unit to 5.5 V ¹² to 2.145 V to 2.1 V to 85 ¹³ °C	
	No See ¹¹ Ratings Over Operation 1 VDD_IN 2 VDDIO_1.8V 3 Input voltage to 4 Operating amb 5 Storage temperation 6 Bluetooth RF in	Note All parameters are measured as follows $VDD_IN^{10} = 3.3 \text{ V}, VDD_IO = 1.8 \text{ V}.$ ing Free-Air Temperature Range Supply voltage range RF (Pin 13) tent temperature range rature range	s unless stated othe Value -0.5 -0.5 -0.5 -40 -40	e Unit to 5.5 V ¹² to 2.145 V to 2.1 V to 85 ¹³ °C to 125 °C	
	No See ¹¹ Ratings Over Operation 1 VDD_IN 2 VDDIO_1.8V 3 Input voltage to 4 Operating amb 5 Storage temperation 6 Bluetooth RF in	Note All parameters are measured as follows VDD_IN ¹⁰ = 3.3 V, VDD_IO = 1.8 V. ing Free-Air Temperature Range Supply voltage range RF (Pin 13) ient temperature range rature range aputs (Pin 13)	s unless stated othe Valu -0.5 -0.5 -0.5 -0.5 -0.5 -0.5 10	e Unit to 5.5 V ¹² to 2.145 V to 2.1 V to 85 ¹³ °C to 125 °C dBm	
	No See ¹¹ Ratings Over Operation 1 VDD_IN 2 VDDIO_1.8V 3 Input voltage to 4 Operating amb 5 Storage temperation 6 Bluetooth RF in	Note All parameters are measured as follows VDD_IN ¹⁰ = 3.3 V, VDD_IO = 1.8 V. ing Free-Air Temperature Range Supply voltage range RF (Pin 13) ient temperature range rature range aputs (Pin 13)	s unless stated othe Valu -0.5 -0.5 -0.5 -0.5 -0.5 -0.5 10	e Unit to 5.5 V ¹² to 2.145 V to 2.1 V to 85 ¹³ °C to 125 °C dBm	
	No See ¹¹ Ratigs Over Operation 1 VDD_IN 2 2 VDDIO_1.8V 3 Input voltage to 4 Operating ambined 5 Storage tempered 6 Bluetooth RF ir 7 ESD: Human B	Note All parameters are measured as follows VDD_IN ¹⁰ = 3.3 V, VDD_IO = 1.8 V. ing Free-Air Temperature Range Supply voltage range RF (Pin 13) ient temperature range rature range uputs (Pin 13) ody Model (HBM). JEDEC 22-A114	s unless stated other Value -0.5 -0.5 -0.5 -0.5 -40 -40 10 500	e Unit to 5.5 V ¹² to 2.145 V to 2.1 V to 85 ¹³ °C to 125 °C dBm V	
¹⁰ VDD_1	No See ¹¹ Ratings Over Operating 1 VDD_IN 2 VDDIO_1.8V 3 Input voltage to 4 Operating amb 5 Storage tempered 6 Bluetooth RF ir 7 ESD: Human B	Note All parameters are measured as follows VDD_IN ¹⁰ = 3.3 V, VDD_IO = 1.8 V. ing Free-Air Temperature Range Supply voltage range RF (Pin 13) ient temperature range rature range puts (Pin 13) ody Model (HBM). JEDEC 22-A114	S unless stated other Value -0.5 -0.5 -0.5 -0.5 -40 -40 10 500	e Unit to 5.5 V ¹² to 2.145 V to 2.1 V to 85 ¹³ °C to 125 °C dBm V hapter 6.3.	ess ratin
¹⁰ VDD_I ¹¹ Stress	No See ¹¹ Ratings Over Operation 1 VDD_IN 2 VDDIO_1.8V 3 Input voltage to 4 Operating ambined 5 Storage tempered 6 Bluetooth RF ir 7 ESD: Human B IN is supplied to MLD ses beyond those lister	Note All parameters are measured as follows VDD_IN ¹⁰ = 3.3 V, VDD_IO = 1.8 V. ing Free-Air Temperature Range Supply voltage range RF (Pin 13) ient temperature range rature range uputs (Pin 13) ody Model (HBM). JEDEC 22-A114 O_IN (Pin 15) and CL1.5_LDO_IN (Pin 11), other of d under "absolute maximum ratings" may cause per	s unless stated other Value -0.5 -0.5 -0.5 -0.5 -0.5 -0.5 -0.5 -0.5	e Unit to 5.5 V ¹² to 2.145 V to 2.1 V to 85 ¹³ °C to 125 °C dBm V hapter 6.3. v	
¹⁰ VDD_1 ¹¹ Stress only ar	No See ¹¹ Ratings Over Operating 1 VDD_IN 2 VDDIO_1.8V 3 Input voltage to 4 Operating amb 5 Storage temperation 6 Bluetooth RF in 7 ESD: Human B	Note All parameters are measured as follows VDD_IN ¹⁰ = 3.3 V, VDD_IO = 1.8 V. ing Free-Air Temperature Range Supply voltage range RF (Pin 13) ient temperature range rature range puts (Pin 13) ody Model (HBM). JEDEC 22-A114	s unless stated other Value -0.5	e Unit to 5.5 V ¹² to 2.145 V to 2.1 V to 3.13 °C to 125 °C dBm V hapter 6.3. v	erating

¹² Maximum allowed depends on accumulated time at that voltage: VDD_IN is defined in Reference schematics. When DC2DC supply is used, maximum voltage into MLDO_OUT and LDO_IN = 2.145 V.

¹³ Older generation parts, which are not recommended for new designs, will support a temperature range -20 to 70. See chapter 28, ordering information, for details.

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10.2 RECOMMENDED OPERATING CONDITIONS

No	Rating	Condition	Symbol	Min	Max	Unit
1	Power supply voltage ¹⁴		VDD_IN	1.7	4.8	V
2	IO power supply voltage		VDD_IO	1.62	1.92	V
3	High-level input voltage	Default	V _{IH}	0.65 x VDD_IO	VDD_IO	V
4	Low-level input voltage	Default	V _{IL}	0	0.35 x VDD_IO	V
5	IO Input rise/fall times, 10% to 90% ¹⁵		Tr/Tf	1	10	ns
		0 to 0.1 MHz			60	
		0.1 to 0.5 MHz			50	
6	Maximum ripple on VDD_IN (Sine wave) for 1.8 V (DC2DC) mode	0.5 to 2.5 MHz			30	mVp-p
		2.5 to 3.0 MHz			15	
		> 3.0 MHz			5	
7	Voltage dips on VDD_IN (V _{BAT}) (duration = $577 \ \mu s$ to 2.31 ms, period = 4.6 ms)				400	mV
8	Maximum ambient operating temperature ¹⁶				85	°C
9	Minimum ambient operating temperature ¹⁷				-40	□C

10.3 CURRENT CONSUMPTION

No	Characteristics	Min 25°C	Typ 25°C	Max 25°C	Min -40°C	Typ -40°C	Max -40°C	Min +85°C	Typ +85°C	Max +85°C	Unit
1	Current consumption in shutdown mode ¹⁸		1	3						7	μA
2	Current consumption in deep sleep mode ¹⁹		40	105						700	μA

¹⁴ Excluding 1.98 < VDD_IN < 2.2 V range – not allowed.

¹⁵ Asynchronous mode.

¹⁶ The device can be reliably operated for 7 years at T_{ambient} of 85°C, assuming 25% active mode and 75% sleep mode (15,400 cumulative active power-on hours).

Older generation parts, which are not recommended for new designs, will support a temperature range -20 to 70. See chapter 28, ordering information, for details.

¹⁷ The device can be reliably operated for 7 years at T_{ambient} of 85°C, assuming 25% active mode and 75% sleep mode (15,400 cumulative active power-on hours).

Older generation parts, which are not recommended for new designs, will support a temperature range -20 to 70. See chapter 28, ordering information, for details.

¹⁸ Vbat + Vio

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No	Characteristics	Min	Typ	Max	Min	Typ	Max	Min	Тур	Max	Unit	

Ν	No	Characteristics	25°C	25°C	25°C	-40°C	-40°C	-40°C	+85°C	тур +85°С	+85°C	Unit
3	3	Total IO current consumption for active mode			1			1			1	mA
4		Current consumption during transmit DH5 full throughput		40								mA

10.4 GENERAL ELECTRICAL CHARACTERISTICS

No	Rating			Condition	Min	Max	Value
4	Link lavel even			at 2/4/8 mA	0.8 x VDD_IO	VDD_IO	V
1	High-level outp	ut voltage, v _{oh}		at 0.1 mA	VDD_IO - 0.2	VDD_IO	V
2		. I		at 2/4/8 mA	0	0.2 x VDD_IO	V
2	Low-level outpu	it voltage, v _{ol}	t voltage, V _{OL}		0	0.2	V
2				Resistance	1		MΩ
3	IO input impeda	ance		Capacitance		5	pF
4	Output rise/fall	times,10% to 909	% (Digital pins)	C _L = 20 pF		10	Ns
		TX_DBG,	PU	typ = 6.5	3.5	9.7	۵
-	IO pull	PCM bus PD		typ = 27	9.5	55	μA
5	currents	PU		typ = 100	100	300	
		All others PD		typ = 100	100	360	μA

10.5 NSHUTD REQUIREMENTS

No	Parameter	Symbol	Min	Max	Unit
1	Operation mode level 20	VIH	1.42	1.98	V
2	Shutdown mode level	V _{IL}	0	0.4	V
3	Minimum time for nSHUT_DOWN low to reset the device		5		ms
4	Rise/fall times	Tr/Tf		20	μs

10.6 EXTERNAL DIGITAL SLOW CLOCK REQUIREMENTS

Ν	lo	Characteristics	Condition	Symbol	Min	Тур	Max	Unit
1		Input slow clock frequency				32768		Hz
2		Input slow clock accuracy (Initial + temp + aging)	Bluetooth				±250	Ppm

¹⁹ Vbat + Vio + Vsd (shutdown)

²⁰ Internal pull down retains shut down mode when no external signal is applied to this pin.

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No	Characteristics	Condition	Symbol	Min	Тур	Max	Unit
3	Input transition time Tr/Tf – 10% to 90%		Tr/Tf			100	Ns
4	Frequency input duty cycle			15%	50%	85%	
5	Phase noise	at 1 kHz				-125	dBc/Hz
6	Jitter	Integrated over 300 to 15000 Hz				1	Hz
	Slow clock input voltage limits	Square wave, DC coupled	VIH	0.65 x VDD_IO		VDD_IO	V peak
7			VIL	0		0.35 x VDD_IO	v peak
8	Input impedance			1			MΩ
9	Input capacitance					5	pF

11 HOST CONTROLLER INTERFACE

The CC256X incorporates one UART module dedicated to the host controller interface (HCI) transport layer. The HCI interface transports commands, events, ACL, and synchronous data between the Bluetooth device and its host using HCI data packets.

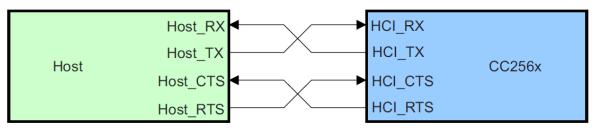
The UART module supports H4 (4-wires) protocol with maximum baud rate of 4 Mbps for all fast clock frequencies.

After power up the baud rate is set for 115.2 kbps, irrespective of fast clock frequency. The baud rate can thereafter be changed with a vendor specific command. The CC256X responds with a Command Complete Event (still at 115.2 kbps), after which the baud rate change takes place. HCI hardware includes the following features:

- Receiver detection of break, idle, framing, FIFO overflow, and parity error conditions
- Transmitter underflow detection
- CTS/RTS hardware flow control

The interface includes four signals: TXD, RXD, CTS, and RTS. Flow control between the host and the CC256X is byte-wise by hardware.

Flow control is obtained by the following:



When the UART RX buffer of the CC256X passes the "flow control" threshold, it will set the UART_RTS signal high to stop transmission from the host.

When the UART_CTS signal is set high, the CC256X will stop its transmission on the interface. In case HCI_CTS is set high in the middle of transmitting a byte, the CC256X will finish transmitting the byte and stop the transmission.

SUBJECT CLASS 1 or 2 BLUETOOTH MODULE PAGE 20 of 55 CUSTOMER'S CODE PAN13XX Core Specification PANASONIC'S CODE See Chapter Ordering Information DATE 08.11.2017 Image: Comparison of the com	CLASSIFICATION	PRODUCT SPECIFICATION	No. DS-13xx-24	400-102	REV. 5.1
PAN13XX Core Specification See Chapter Ordering Information DATE 08.11.2017 12 AUDIO/VOICE CODEC INTERFACE The codec interface is a fully-dedicated programmable serial port that provides the logic to interface to several kinds of PCM or I2S codec's. PAN13XX supports all voice coding schemes required by Bluetooth specification – Log PCM (A-Law or μ-Law) and Linear (CVSD). In addition, module also supports transparent scheme: • Two voice channels • Master / slave modes • μ-Law, A-Law, Linear, Transparent coding schemes • Long and short frames • Different data sizes, order, and positions. • High rate PCM interface for EDR • Enlarged interface options to support a wider variety of codecs	SUBJECT CLASS	1 or 2 BLUETOOTH MODULE	PAGE	20 of	55
 The codec interface is a fully-dedicated programmable serial port that provides the logic to interface to several kinds of PCM or I2S codec's. PAN13XX supports all voice coding schemes required by Bluetooth specification – Log PCM (A-Law or µ-Law) and Linear (CVSD). In addition, module also supports transparent scheme: Two voice channels Master / slave modes µ-Law, A-Law, Linear, Transparent coding schemes Long and short frames Different data sizes, order, and positions. High rate PCM interface for EDR Enlarged interface options to support a wider variety of codecs 					017
	The codec interface is interface to several ki required by Bluetooth spe also supports transparent • Two voice channels • Master / slave modes • μ-Law, A-Law, Linear • Long and short frame • Different data sizes, o • High rate PCM interfa • Enlarged interface op	s a fully-dedicated programmable serial nds of PCM or I2S codec's. PAN13XX s ecification – Log PCM (A-Law or µ-Law) and scheme: , Transparent coding schemes s order, and positions. Ice for EDR	supports all voice	e coding schem	nes

The PCM interface is one implementation of the codec interface. It contains the following four lines:

- Clock configurable direction (input or output)
- Frame Sync configurable direction (input or output)
- Data In Input
- Data Out Output/3-state

The Bluetooth device can be either the master of the interface where it generates the clock and the frame-sync signals, or slave where it receives these two signals. The PCM interface is fully configured by a vendor specific command.

For slave mode, clock input frequencies of up to 16 MHz are supported. At clock rates above 12 MHz, the maximum data burst size is 32 bits. For master mode, the CC256X can generate any clock frequency between 64 kHz and 6 MHz.

When the I2S bus is used in an application, Panasonic recommends adding a low pass filter (series resistor and capacitor to GND) to the bus for better noise suppression. Connecting the host μ Controller/DSP directly with the module's I2S interface is not recommended.

The suggested low pass filter component values are:

470pf 120 ohms

12.2 DATA FORMAT

The data format is fully configurable:

• The data length can be from 8 to 320 bits, in 1-bit increments, when working with two channels, or up to 640 bits when using 1 channel. The Data length can be set independently for each channel.

• The data position within a frame is also configurable in with 1 clock (bit) resolution and can be set independently (relative to the edge of the Frame Sync signal) for each channel.

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• The Data_In and Data_Out bit order can be configured independently. For example; Data_In can start with the MSB while Data_Out starts with LSB. Each channel is separately configurable. The inverse bit order (that is, LSB first) is supported only for sample sizes up to 24 bits.

• It is not necessary for the data in and data out size to be the same length.

• The Data_Out line is configured to 'high-Z' output between data words. Data_Out can also be set for permanent high-Z, irrespective of data out. This allows the CC256X to be a bus slave in a multi-slave PCM environment. At power up, Data Out is configured as high-Z.

12.3 FRAME IDLE PERIOD

The codec interface has the capability for frame idle periods, where the PCM clock can "take a break" and become '0' at the end of the PCM frame, after all data has been transferred.

The CC256X supports frame idle periods both as master and slave of the PCM bus.

When CC256X is the master of the interface, the frame idle period is configurable. There are two configurable parameters:

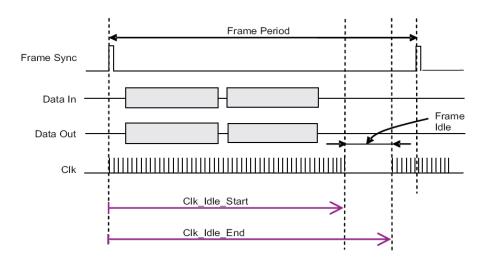
• Clk_Idle_Start – Indicates the number of PCM clock cycles from the beginning of the frame until the beginning of the idle period. After Clk_Idle_Start clock cycles, the clock will become '0'.

• Clk_Idle_End – Indicates the time from the beginning of the frame till the end of the idle period. This time is given in multiples of PCM clock periods.

The delta between Clk_Idle_Start and Clk_Idle_End is the clock idle period.

For example, for PCM clock rate = 1 MHz, frame sync period = 10 kHz, Clk_Idle_Start = 60, Clk_Idle_End = 90.

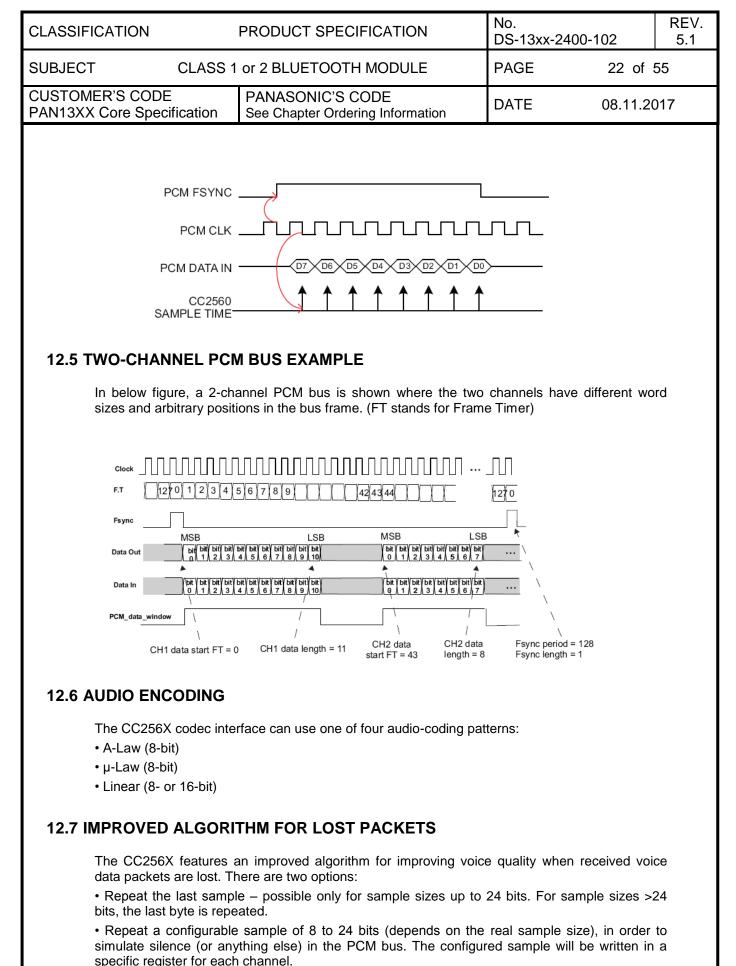
Between each two frame syncs there are 70 clock cycles (instead of 100). The clock idle period starts 60 clock cycles after the beginning of the frame, and lasts 90 - 60 = 30 clock cycles. This means that the idle period ends 100 - 90 = 10 clock cycles before the end of the frame. The data transmission must end prior to the beginning of the idle period.



12.4 CLOCK-EDGE OPERATION

The codec interface of the CC256X can work on the rising or the falling edge of the clock. It also has the ability to sample the frame sync and the data at inversed polarity.

This is the operation of a falling-edge-clock type of codec. The codec is the master of the PCM bus. The frame sync signal is updated (by the codec) on the falling clock edge and therefore shall be sampled (by the CC256X) on the next rising clock. The data from the codec is sampled (by the CC256X) on the clock falling edge.



The choice between those two options is configurable separately for each channel.

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12.8 BLUETOOTH/PCM CLOCK MISMATCH HANDLING

In Bluetooth RX, the CC256X receives RF voice packets and writes these to the codec I/F. If the CC256X receives data faster than the codec I/F output allows, an overflow will occur. In this case, the Bluetooth has two possible behaviour modes: 'allow overflow' and 'don't allow overflow'.

• If overflow is allowed, the Bluetooth will continue receiving data and will overwrite any data not yet sent to the codec.

• If overflow is not allowed, RF voice packets received when buffer is full will be discarded.

12.9 BLUETOOTH INTER-IC SOUND (I2S)

The CC256X can be configured as an Inter-IC Sound (I2S) serial interface to an I2S codec device. In this mode, the CC256X audio codec interface is configured as a bi-directional, full-duplex interface, with two time slots per frame: Time slot 0 is used for the left channel audio data and time slot 1 for the right channel audio data. Each time slot is configurable up to 40 serial clock cycles in length and the frame is configurable up to 80 serial clock cycles in length.

Do not connect the microcontroller/DSP directly to the module's PCM interface, a simple RC low pass filter is recommended to improve noise suppression.

12.10 CURRENT CONSUMPTION FOR DIFFERENT BLUETOOTH SCENARIOS

The following table gives average current consumption for different Bluetooth scenarios. Conditions: VDD IN = 3.6 V, 25°C , 26°MHz fast clock, nominal unit, 4 dBm output power.

Mode Description	Master/Slave	Average Current	Unit
Idle current (ARM off)	Master/Slave	2.5	mA
SCO link HV3	Master/Slave	12	mA
eSCO link EV3 64 kbps, no retransmission	Master/Slave	11.5	mA
eSCO link 2-EV3 64 kbps, no retransmission	Master/Slave	8.3	mA
GFSK full throughput: TX = DH1, RX = DH5	Master/Slave	38.5	mA
EDR full throughput: TX = 2-DH1, RX = 2-DH5	Master/Slave	39.2	mA
EDR full throughput: TX = 3-DH1, RX = 3-DH5	Master/Slave	39.2	mA
Sniff, 1 attempt, 1.28 s	Master/Slave	76/100	μA
Page or Inquiry Scan 1.28 s, 11.25 ms	Master/Slave	300	μA
Page (1.28 s) and Inquiry (2.56 s) scans, 11.25 ms	Master/Slave	430	μA
Low power scan, 1.28-s interval, quiet environment	Master/Slave	135	μΑ

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13 BLUETOOT	H RF PER	FORMANCE					
No Ch	naracteristics			BI Spec	BI Spec		
			Тур	BT Spec Max	BT Spec Min		
1 Av		lopping DH5 [dBm] ^{22, 23}	Тур 7.2				
	verage Power H	Hopping DH5 [dBm] ^{22, 23} Ch0 [dBm] ^{22, 23}		Max Class1	Min Class1		
2 Av	verage Power H	Ch0 [dBm] ^{22, 23}	7.2	Max Class1 20	Min Class1 4		

No	Characteristics	Тур	BT Spec Max	BT Spec Min
			Class1	Class1
1	Average Power Hopping DH5 [dBm] 22, 23	7.2	20	4
2	Average Power: Ch0 [dBm] ^{22, 23}	7.5	20	4
3	Peak Power: Ch0 [dBm] 22, 23	7.7	23	
4	Average Power: Ch39 [dBm] ^{22, 23}	7.0	20	4
5	Peak Power: Ch39 [dBm] 22, 23	7.2	23	
6	Average Power: Ch78 [dBm] 22, 23	6.7	20	4
7	Peak Power: Ch78 [dBm] 22, 23	7.0	23	
8	Max. Frequency Tolerance: Ch0 [kHz]	-2.6	75	-75
9	Max. Frequency Tolerance: Ch39 [kHz]	-2.2	75	-75
10	Max. Frequency Tolerance: Ch78 [kHz]	-2.1	75	-75
11	Max. Drift: Ch0_DH1 [kHz]	3.6	25	-25
12	Max. Drift: Ch0_DH3 [kHz]	3.7	40	-40
13	Max. Drift: Ch0_DH5 [kHz]	4.0	40	-40
14	Max. Drift Rate: Ch0_DH1 [kHz]	-2.6	20	-20
15	Max. Drift Rate: Ch0_DH3 [kHz]	-3.2	20	-20
16	Max. Drift Rate: Ch0_DH5 [kHz]	-3.3	20	-20
17	Max. Drift: Ch39_DH1 [kHz]	4.0	25	-25
18	Max. Drift: Ch39_DH3 [kHz]	4.3	40	-40
19	Max. Drift: Ch39_DH5 [kHz]	4.3	40	-40
20	Max. Drift Rate: Ch39_DH1 [kHz]	-3.1	20	-20
21	Max. Drift Rate: Ch39_DH3 [kHz]	-3.6	20	-20
22	Max. Drift Rate: Ch39_DH5 [kHz]	-3.7	20	-20
23	Max. Drift: Ch78_DH1 [kHz]	4.1	25	-25
24	Max. Drift: Ch78_DH3 [kHz]	4.5	40	-40
25	Max. Drift: Ch78_DH5 [kHz]	4.4	40	-40
26	Max. Drift Rate: Ch78_DH1 [kHz]	-3.4	20	-20
27	Max. Drift Rate: Ch78_DH3 [kHz]	-3.9	20	-20
28	Max. Drift Rate: Ch78_DH5 [kHz]	-4.1	20	-20
29	Delta F1 Avg: Ch0 [kHz]	159.5	175	140
30	Delta F2 Max.: Ch0 [%]	100.0		99.9
31	Delta F2 Avg/Delta F1 Avg: Ch0	0.9		0.8
32	Delta F1 Avg: Ch39 [kHz]	159.8	175	140
33	Delta F2 Max.: Ch39 [%]	100.0		99.9
34	Delta F2 Avg/Delta F1 Avg: Ch39	0.9		0.8
35	Delta F1 Avg: Ch78 [kHz]	159.1	175	140
36	Delta F2 Max.: Ch78 [%]	100.0		99.9
37	Delta F2 Avg/Delta F1 Avg: Ch78	0.9		0.8
45	Sensitivity	-93.0		-81
46	f(H)-f(L): Ch0 [kHz]	918.4	1000	
47	f(H)-f(L): Ch39 [kHz]	918.3	1000	
48	f(H)-f(L): Ch78 [kHz]	918.2	1000	
49	ACPower -3: Ch3 [dBm]	-51.5	-40	
50	ACPower -2: Ch3 [dBm]	-50.4	-40	

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SUBJECT		1 or 2 BLUETOOTH M		PAG	E	25 of	55
CUSTOMER'S CO PAN13XX Core S		PANASONIC'S COL See Chapter Ordering		DATE	Ξ	08.11.20	017
					-		
No	Characteristics		Тур	BT Spec Max	BT Spec Min		
				Class1	Class1		
51	ACPower -1: Cl	h3 [dBm]	-18.5		ļ		
52		• •	8.1	20	4		
53			-19.2	<u> </u>	<u> </u>		
54		• •	-50.7	-40	───┤		
55			-53.3	-40			
56			-51.6	-40	┨────┤		
57			-50.7	-40	┼───┤		
<u>58</u> 59			-19.0	20	4		
<u> </u>			-19.7	20	4		
61	ACPower +1: C		-50.9	-40	<u> </u>		
62			-53.2	-40	<u> </u>		
63		• •	-51.7	-40	1		
64			-50.7	-40			
65			-19.2				
66			7.5	20	4		
67			-20.0	1			
68			-51.0	-40			
69	ACPower +3: C	;h75 [dBm]	-53.4	-40			
70	omega i 2-DH5	: Ch0 [kHz]	-4.7	75	-75		
71	omega o + ome	ega i 2-DH5: Ch0 [kHz]	-6.0	75	-75		
72	omega o 2-DH5	5: Ch0 [kHz]	-1.5	10	-10		
73	DEVM RMS 2-	DH5: Ch0 [%]	0.0	0.2	ļ		
74	DEVM Peak 2-I	DH5: Ch0 [%]	0.1	0.35	<u> </u>		
75		• •	100.0		99		
76	v		-3.7	75	-75		
77		ega i 3-DH5: Ch0 [kHz]	-5.8	75	-75		
78	v	• •	-2.6	10	-10		
79			0.0	0.13			
80			0.1	0.25			
81			-4.8	75	99 -75		
<u>82</u> 83		: Сп39 [кнz] ega i 2-DH5: Ch39 [kHz]	-4.8	75 75	-75 -75		
84		• • • •	-0.1	10	-10		
85			0.0	0.2	-10		
86			0.0	0.35	<u> </u>		
87		• •	100.0	0.00	99		
88			-3.8	75	-75		
89		ega i 3-DH5: Ch39 [kHz]	-5.9	75	-75		
90		-	-2.6	10	-10		
91	DEVM RMS 3-	DH5: Ch39 [%]	0.0	0.13			
92	DEVM Peak 3-I	DH5: Ch39 [%]	0.1	0.25			
93	DEVM 99% 3-D)H5: Ch39 [%]	100.0		99		
94	omega i 2-DH5	: Ch78 [kHz]	-4.9	75	-75		
95		ega i 2-DH5: Ch78 [kHz]	-6.2	75	-75		

CLASSIFICATION	CLASSIFICATION		TION PRODUCT SPECIFICATION		No. DS-1	3xx-2400)-102	REV. 5.1
SUBJECT	UBJECT CLASS 1		1 or 2 BLUETOOTH MODULE		E	26 of \$	55	
CUSTOMER'S CO PAN13XX Core Sp		PANASONIC'S CODE See Chapter Ordering In		DATE	Ξ	08.11.20)17	
				BT Spec	BT Spec			
No	Characteristics		Тур	Max	Min			
				Class1	Class1			
96	omega o 2-DH5	: Ch78 [kHz]	-1.4	10	-10			
97	DEVM RMS 2-D	0H5: Ch78 [%]	0.0	0.2				
98	DEVM Peak 2-D	DH5: Ch78 [%]	0.1	0.35				
99	DEVM 99% 2-D	H5: Ch78 [%]	100.0		99			
100	omega i 3-DH5:	Ch78 [kHz]	-3.8	75	-75			
101	omega o + ome	ga i 3-DH5: Ch78 [kHz]	-6.0	75	-75			
				1	1			

0.0

0.1

100.0

0.13

0.25

99

	-			_			
No	Characteristics	Condition	Min	Тур	Max	BT Spec	Unit
1	Operation frequency range		2402		2480		MHz
2	Channel spacing			1			MHz
3	Input impedance			50			Ω
		GFSK, BER = 0.1%		-93.0		-70	
4	Sensitivity, Dirty Tx on	Pi/4-DQPSK, BER = 0.01%		-92.5		-70	dBm
		8DPSK, BER = 0.01%		-85.5		-70]

103 DEVM RMS 3-DH5: Ch78 [%]

104 DEVM Peak 3-DH5: Ch78 [%]

105 DEVM 99% 3-DH5: Ch78 [%]

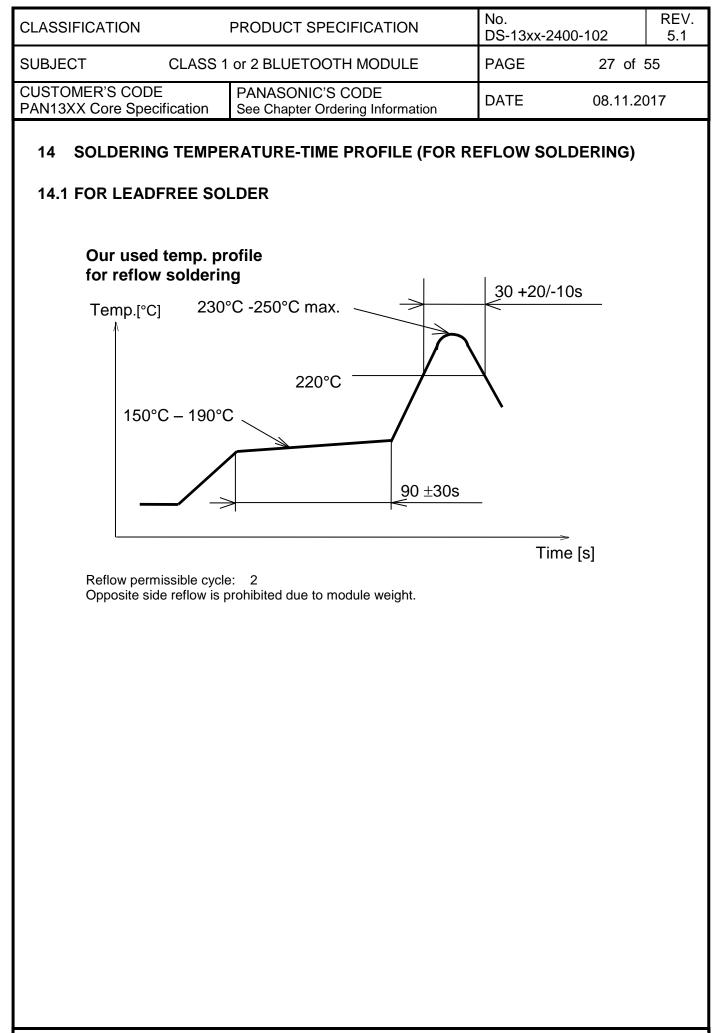
				-	
No	Characteristics	Condition	Тур	Max	Unit
1	The and the out of barra officients	30 kHz to 1 GHz ²¹ , ²² , ²³		-30	dBm
		1 to 12.75 GHz ^{21, 22, 23}		-30	
2	2 nd harmonic	at 7dBm output power ^{21, 22, 23}		-30	dBm
3	3 rd harmonic	at 7dBm output power ^{21, 22, 23}		-30	dBm

The values are measured conducted. Better suppression of the spurious emissions with an antenna can be expected as, antenna frequently have band pass filter characteristics.

²¹ Includes effects of frequency hopping

²³ +7dBm related to power register value 18, according to TI service pack 2.30

²² Average according FCC, IC and ETSI requirements. Above +7dBm output power (refer also to 23) the customer has to verify the final product against national regulations.



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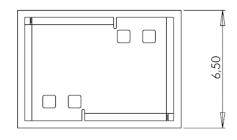
15 MODULE DIMENSION

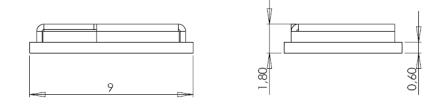
15.1 MODULE DIMENSIONS PAN131X WITHOUT ANTENNA

No.	Item	Dimension	Tolerance	Remark
1	Width	6.50	± 0.20	
2	Lenght	9.00	± 0.20	
3	Height	1.80	± 0.20	With case

15.1.1 PAN131X Module Drawing







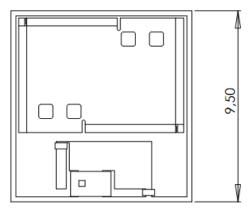
CLASSIFICATION	PRODUCT SPECIFICATION	No. DS-13xx-2400-	102	REV. 5.1
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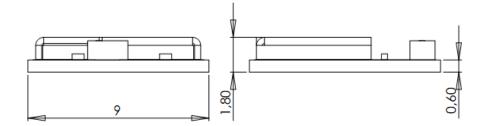
15.2 MODULE DIMENSIONS PAN132X WITH ANTENNA

No.	Item	Dimension	Tolerance	Remark
1	Width	9.50	± 0.20	
2	Lenght	9.00	± 0.20	
3	Height	1.80	± 0.20	With case

15.2.1 PAN132X Module Drawing

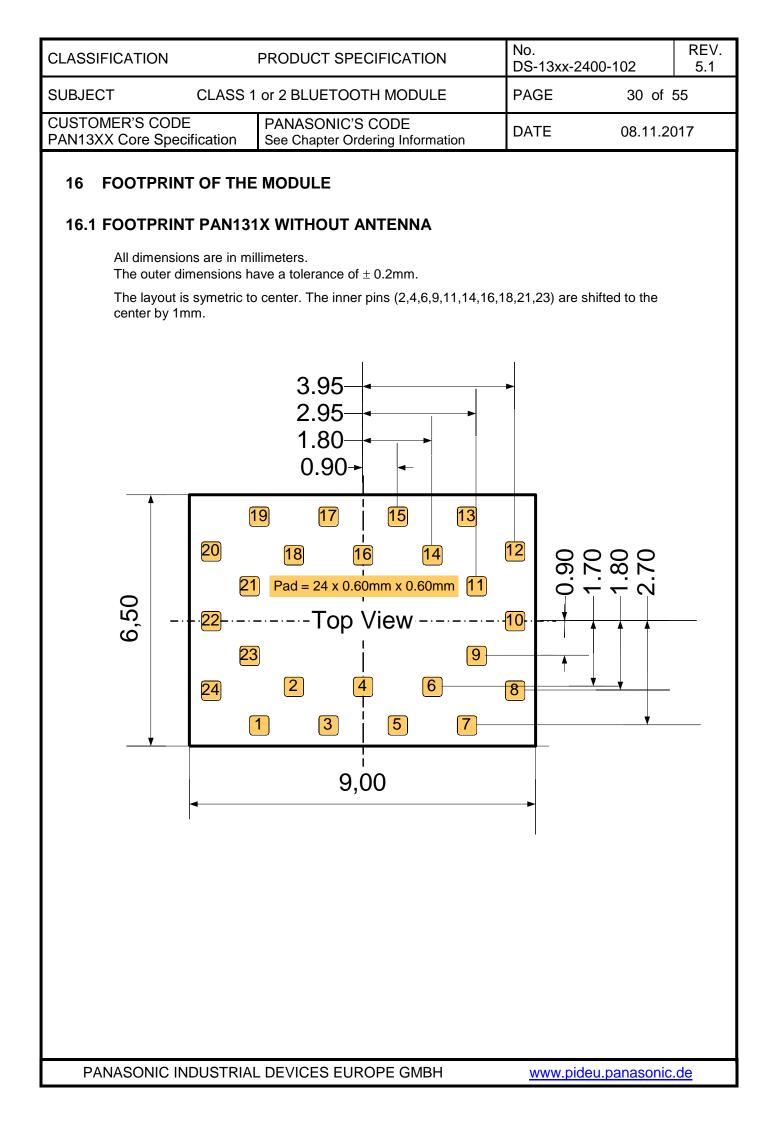


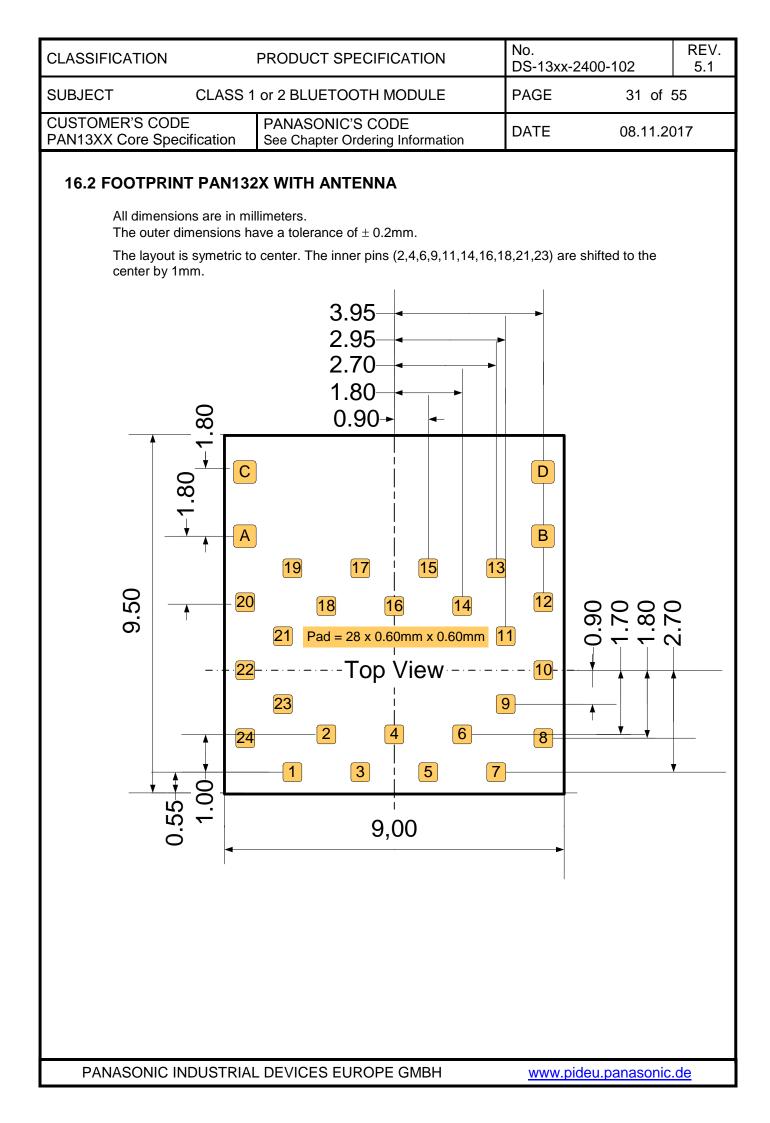


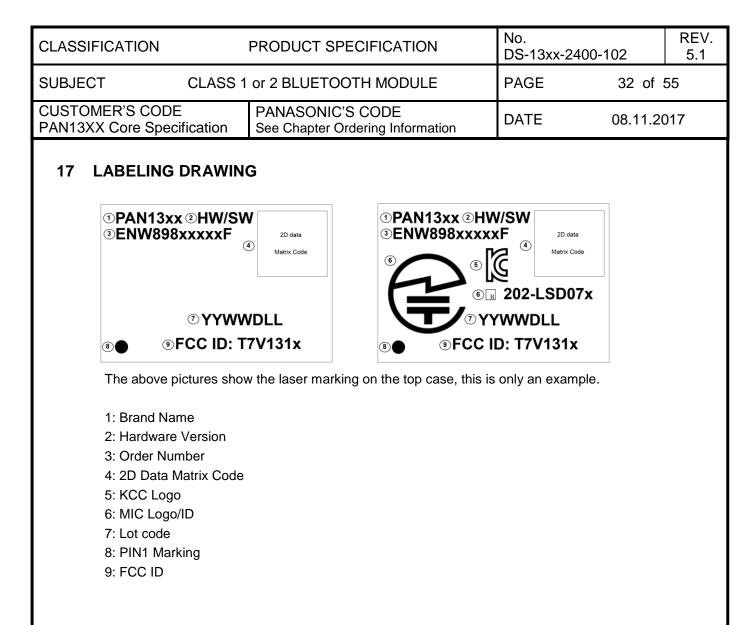


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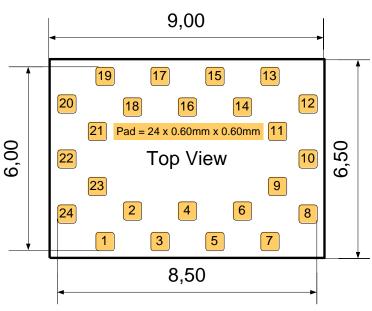




18 MECHANICAL REQUIREMENTS

No.	Item	Limit	Condition
1	Solderability	More than 75% of the soldering area shall be coated by solder	Reflow soldering with recommendable temperature profile
2	Resistance to soldering heat	It shall be satisfied electrical requirements and not be mechanical damage	See Chapter 14.1

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CUSTOMER'S CODE PAN13XX Core Specification	PANASONIC'S CODE See Chapter Ordering Information	DATE	08.11.2017			
19 RECOMMENDED FOOT PATTERN						
19.1 RECOMMENDED FOOT PATTERN PAN131X WITHOUT ANTENNA						
Dimensions in mm.						



The land pattern dimensions above are meant to serve only as a guide. This information is provided without any legal liability.

For the solder paste screen, use as a first guideline the same foot print as shown in the figure above. Solder paste screen cutouts (with slightly different dimensions) might be optimum depending on your soldering process. For example, the solder paste screen thickness chosen might have an effect. The solder screen thickness depends on your production standard 120µm to 150µm is recommended.

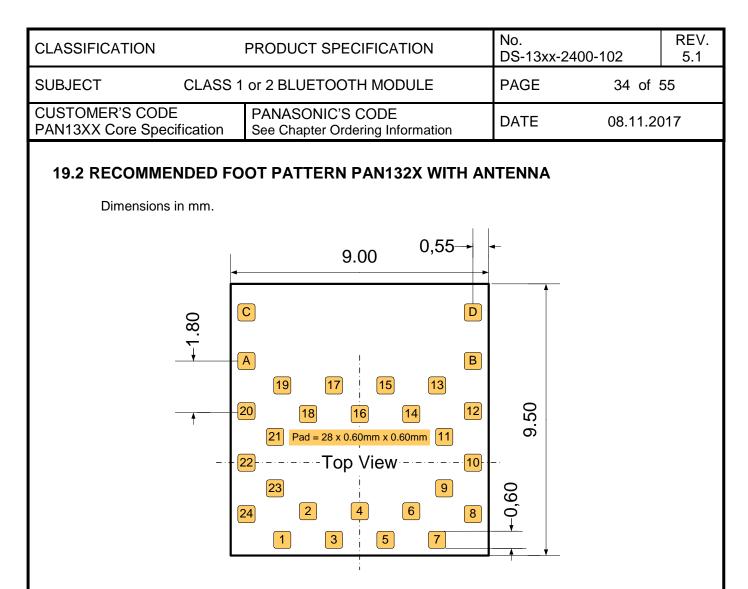
IMPORTANT:

Although the bottom side of PAN131X is fully coated, no copper such as through hole vias, planes or tracks on the board component layer should be located below the PAN131X to avoid creating a short. In cases where a track or through hole via has to be located under the module, it must be kept away from PAN131X bottom pads. The PAN131X multilayer pcb contains an inner RF shielding plane, therefore no pcb shielding plane below the module is needed.

When using an onboard ceramic antenna, place the antenna on the edge of your carrier board (if allowable).

If you have any questions on these points, contact your local Panasonic representative.

Schematics and layouts may be sent to <u>wireless@eu.panasonic.com</u> for final review.



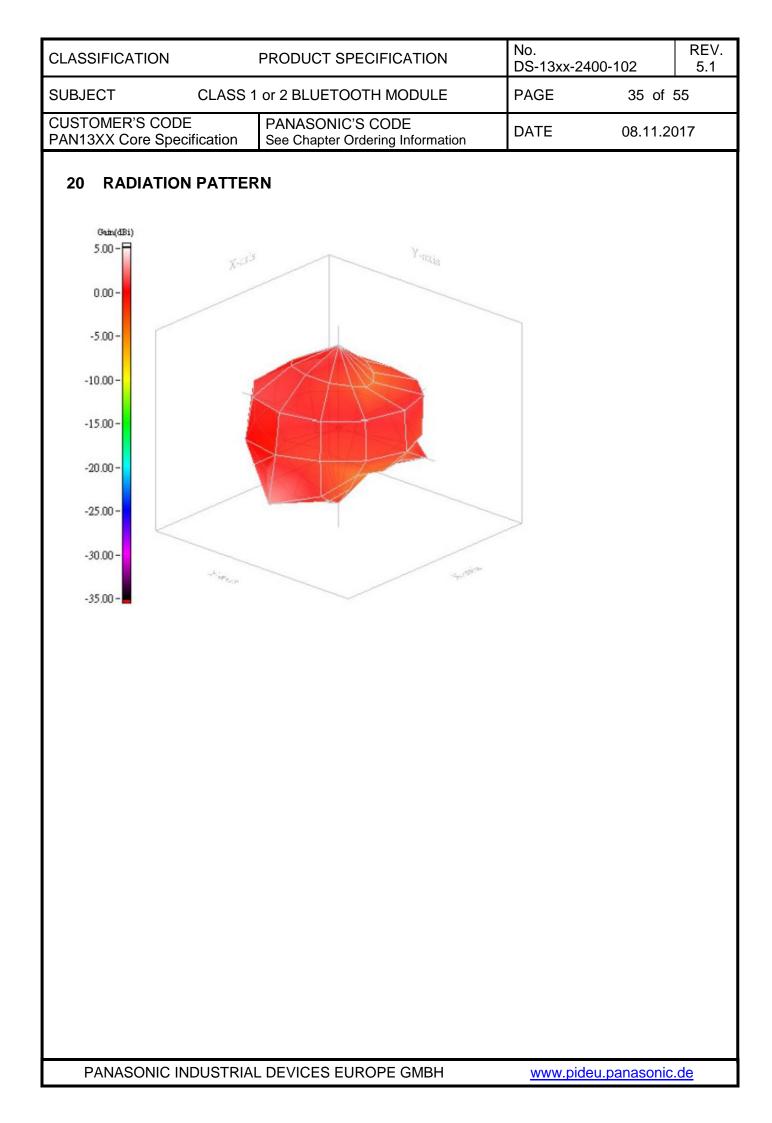
The land pattern dimensions above are meant to serve only as a guide.

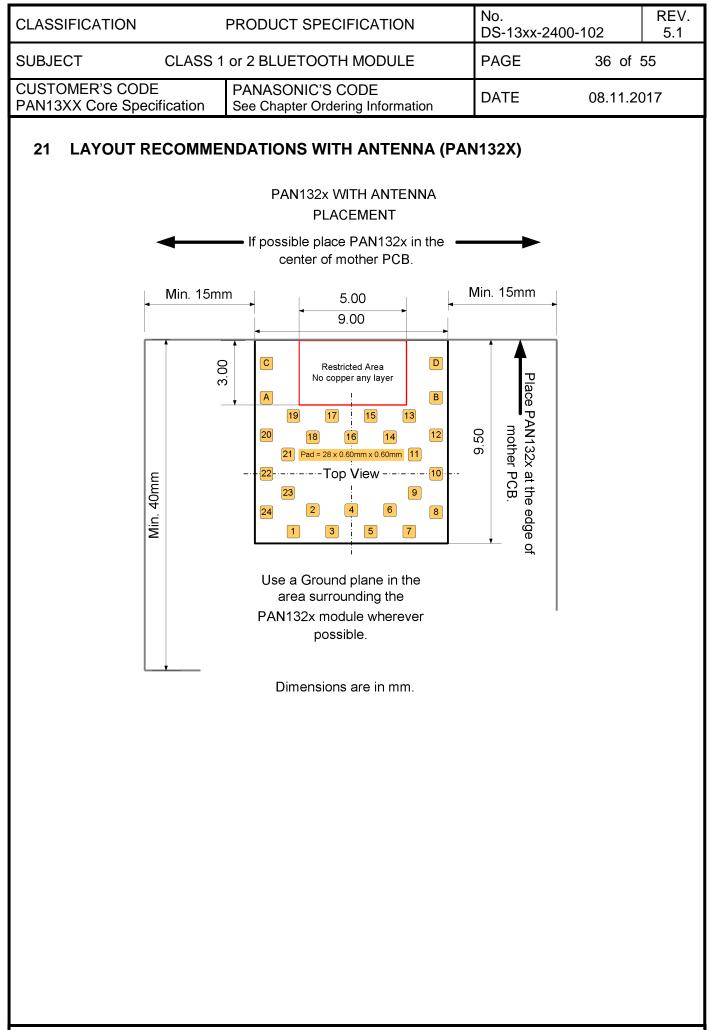
For the solder paste screen, use as a first guideline the same foot print as shown in the Figure above. Solder paste screen cutouts (with slightly different dimensions) might be optimum depending on your soldering process. For example, the solder paste screen thickness chosen might have an effect. The solder screen thickness depends on your production standard 120µm to 150µm is recommended.

IMPORTANT: In cases where a track or through hole via has to be located under the module, it must be kept away from PAN132X bottom pads. The PAN132X multilayer pcb contains an inner RF shielding plane, therefore no pcb shielding plane below the module is needed.

If you have any questions on these points, contact your local Panasonic representative.

Schematics and layouts may be sent to <u>wireless@eu.panasonic.com</u> for final review.





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22 BLUETOOTH LE (LOW ENERGY) PAN1316/26

22.1 NETWORK TOPOLOGY

Bluetooth Low Energy is designed to reduce power consumption. It can be put into a sleep mode and is only activated for event activities such as sending files to a gateway, PC or mobile phone. Furthermore the maximum power consumption is set to less than 15 mA and the average power consumption is about 1 uA. The benefits of low energy consumption are short messages and establishing very fast connections (few ms). Using these techniques, energy consumption is reduced to a tenth of a Classic Bluetooth unit. Thus, a small coin cell – such as a CR2032 – is capable of powering a device for up to 10 years of operation.

To be backwards compatible with Classic Bluetooth and to be able to offer an affordable solution for very inexpensive devices, Panasonic Low Energy Bluetooth modules are offered in two versions:

Dual-mode: Bluetooth Low Energy technology combined with Classic Bluetooth functionality on a single module. Dual mode devices act as gateways between these two technologies.

Single Mode: Bluetooth Low Energy technology to optimize power consumption, which is particularly useful for products powered by small batteries. These modules have embedded controllers allowing the module to operate autonomously in low cost applications that lack intelligence.

22.2 MODULE FEATURES

Fully compliant with Bluetooth 4.0:

- Optimized for proximity and sports use
- Supports up to 10 simultaneous connections
- Multiple sniff instances are tightly coupled to minimize power consumption
- Independent buffering allows a large number of multiple connections without affecting BR/EDR performance
- Includes built-in coexistence and prioritization handling for BR/EDR and LE

22.3 CURRENT CONSUMPTION FOR DIFFERENT LE SCENARIOS

Conditions: VDD_IN = 3.6 V, 25°C, 26-MHz fast clock, nominal unit, 10 dBm output power

Mode	Description	Average Current	Unit
Advertising, non-connectable	Advertising in all 3 channels 1.28msec advertising interval 15Bytes advertise Data	104	μA
Advertising, discoverable	Advertising in all 3 channels 1.28msec advertising interval 15Bytes advertise Data	121	μA
Scanning	Listening to a single frequency per window 1.28msec scan interval 11.25msec scan window	302	μA
Connected (master role)	500msec connection interval 0msec Slave connection latency Empty Tx/Rx LL packets	169	μA

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23 ANT PAN1317/27

ANT+ (sometimes ANT + or ANT Plus) is an interoperability function that can be added to the base ANT protocol (a proprietary wireless sensor network technology).

23.1 NETWORK TOPOLOGY

ANT[™] is a wireless sensor network protocol operating in the 2.4 GHz spectrum. Designed for ultralow power, ease of use, efficiency and scalability, ANT supports peer-to-peer, star, tree and fixed mesh topologies. It provides reliable data communications, flexible and adaptive network operation and cross-talk immunity. The ANT protocol stack is compact, requiring minimal microcontroller resources to reduce system costs, lighten the computational burden and improve efficiency. Lowlevel security is implemented to allow user-defined network security.

PAN1317/1327 provides the first wireless, single-chip solution with dual-mode ANT and Bluetooth connectivity with inclusion of TI's CC2564 device. This solution wirelessly connects 13 million ANT-based devices to the more than 3 billion Bluetooth endpoint devices used by people every day, creating new market opportunities for companies building ANT products and Bluetooth products alike. CC2564 requires 80% less board area than a design with two single-mode solutions (one ANT+, one Bluetooth) and increases the wireless transmission range up to two times the distance of a single-mode ANT+ solution.

23.2 MODULE FEATURES

Fully compliant with ANT protocol:

- ANT solution optimized for fitness, health and consumers use cases
- Supports up to eight simultaneous connections, various network topologies and high-resolution proximity pairing
- Includes built-in coexistence and prioritization handling for BR/EDR and ANT

Features	Benefits
Dual-mode ANT+ and Bluetooth (Bluetooth v2.1 + EDR) on a single chip	 Requires 80% less board area than any dual module or device design Reduces costs associated with incorporating two wireless technologies
Fully validated optimized single antenna solution	 Enables simultaneous operation of ANT+ and Bluetooth without the need for two devices or modules Includes built-in coexistence
Best-in-class Bluetooth and ANT RF performance: - +10 dBm Tx power with transmit power control 93 dBm sensitivity	 Delivers twice the distance between the aggregator and ANT sensor device than competitive single-mode ANT solutions Enables a robust and high-throughput connection with extended range
Support for: - ANT+ ultra low power (master and slave devices) - Bluetooth power saving modes (park, sniff, hold) - Bluetooth ultra low power modes (deep sleep, power down)	- Improves battery life and power efficiency of the finished product
Turnkey solution:	- Ease of integration into system allows quick time to market

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 Fully integrated m Complete develop documentation TI MSP430 hardv integration (optional) 	pment kit with s vare and softwa		- Reduces costs and time assoc	ciated with certific	cation	

23.3 ANT CURRENT CONSUMPTION

Mode	Description	Average Current	Unit
Rx message mode	250msec interval	380	μΑ
Rx message mode	500msec interval	205	μA
Rx message mode	1000msec interval	118	μA

24 TRIPLE MODE (BR/EDR + BLUETOOTH LOW ENERGY OR ANT) PAN1323

The PAN1323 has been engineered to give designers the flexibility to implement Bluetooth Classic (BR/EDR), Bluetooth Low Energy or ANT into an application using a single module, reducing cost and footprint area. Refer to the paragraphs above for complete descriptions on each of the three protocols. The module is fully hardware compatible with the PAN1315, 16, 17, 25, 26 and 27. A highly efficent single RF block serves all three protocols. Protocols access the RF block using time division multiplexing. The application layer determines the priority and timing of the RF block. Customers interested in this unique module are encouraged to contact StoneStreetOne for a Bluetooth SIG certified stack. Note ANT and BLE can not be used simultaniously.

24.1 TRIPLE MODE CURRENT CONSUMPTION

The current consumption of the PAN1323 is a function of the protocol that the module is running at any point in time. Refer to the paragraphs above for details on current consumption for each of the three protocols or software vendor.

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For software versic www.panasonic.co	OF APPLICATIONS ons visit the following links: m/rfmodules iki.ti.com/index.php/CC256x_F	Forum Guidelin	es and FAQs		
25.1 TOOLS TO BE N	EEDED				
Tool		Source			
	38 – Experimenter Board	MSP-EXP4	30F5438		
	430 – Debugging Interface	MSP-FET4			
PAN1323EMK - Bluet	ooth Evaluation Module Kit for MSP43	30 TI <u>PAN1323</u> Panasonic <u>PA</u>			
			AS RUMENTS 430		
MSP-EXP430F54 MSP430F5438 E	AS AS AS AS AS AS AS AS AS AS	nvironment, e.g	PAN1323ET		
http://processors.w	iki.ti.com/index.php/CC256x_E iki.ti.com/index.php/CC256x_F				
Evaluation kits and	modules are available througl y additional information, pleas	n Panasonic's n	etwork of autho		
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26 RELIABILITY TESTS

The measurement should be done after being exposed to room temperature and humidity for 1 hour.

No.	Item	Limit	Condition
1	Vibration test	Electrical parameter should be in specification	a) Freq.:10~50Hz,Amplitude:1.5mm a) 20min. / cycle,1hrs. each of XYZ axis b) Freq.:30~100Hz, 6G b) 20min. / cycle,1hrs. each of XYZ axis
2	Shock test	the same as above	Dropped onto hard wood from height of 50cm for 3 times
3	Heat cycle test	the same as above	-40°C for 30min. and +85°C for 30min.; each temperature 300 cycles
4	Moisture test	the same as above	+60°C, 90% RH, 300h
5	Low temp. test	the same as above	-40°C, 300h
6	High temp. test	the same as above	+85°C, 300h

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27 CAUTIONS

Failure to follow the guidelines set forth in this document may result in degrading of the product's functions and damage to the product.

27.1 DESIGN NOTES

- (1) Follow the conditions written in this specification, especially the control signals of this module.
- (2) The supply voltage has to be free of AC ripple voltage (for example from a battery or a low noise regulator output). For noisy supply voltages, provide a decoupling circuit (for example a ferrite in series connection and a bypass capacitor to ground of at least 47uF directly at the module).
- (3) This product should not be mechanically stressed when installed.
- (4) Keep this product away from heat. Heat is the major cause of decreasing the life of these products.
- (5) Avoid assembly and use of the target equipment in conditions where the products' temperature may exceed the maximum tolerance.
- (6) The supply voltage should not be exceedingly high or reversed. It should not carry noise and/or spikes.
- (7) Keep this product away from other high frequency circuits.

27.2 INSTALLATION NOTES

- (1) Reflow soldering is possible twice based on the conditions in Chapter 15. Set up the temperature at the soldering portion of this product according to this reflow profile.
- (2) Carefully position the products so that their heat will not burn into printed circuit boards or affect the other components that are susceptible to heat.
- (3) Carefully locate these products so that their temperatures will not increase due to the effects of heat generated by neighboring components.
- (4) If a vinyl-covered wire comes into contact with the products, then the cover will melt and generate toxic gas, damaging the insulation. Never allow contact between the cover and these products to occur.
- (5) This product should not be mechanically stressed or vibrated when reflowed.
- (6) To repair a board by hand soldering, keep the conditions of this chapter.
- (7) Do not wash this product.
- (8) Refer to the recommended pattern when designing a board.
- (9) Pressing on parts of the metal cover or fastening objects to the metal will cause damage to the unit.

27.3 USAGE CONDITIONS NOTES

- (1) Take measures to protect the unit against static electricity. If pulses or other transient loads (a large load applied in a short time) are applied to the products, check and evaluate their operation befor assembly on the final products.
- (2) Do not use dropped products.
- (3) Do not touch, damage or soil the pins.

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- (4) Follow the recommended condition ratings about the power supply applied to this product.
- (5) Electrode peeling strength: Do not add pressure of more than 4.9N when soldered on PCB.
- (6) Pressing on parts of the metal cover or fastening objects to the metal cover will cause damage.
- (7) These products are intended for general purpose and standard use in general electronic equipment, such as home appliances, office equipment, information and communication equipment.

27.4 STORAGE NOTES

- (1) The module should not be stressed mechanically during storage.
- (2) Do not store these products in the following conditions or the performance characteristics of the product, such as RF performance will be adversely affected:
 - Storage in salty air or in an environment with a high concentration of corrosive gas, such as Cl2, H2S, NH3, SO2, or NOX
 - Storage in direct sunlight
 - Storage in an environment where the temperature may be outside the range of 5°C to 35°C range, or where the humidity may be outside the 45 to 85% range.
 - Storage of the products for more than one year after the date of delivery Storage period: check the adhesive strength of the embossed tape and soldering after 6 months of storage.
- (3) Keep this product away from water, poisonous gas and corrosive gas.
- (4) This product should not be stressed or shocked when transported.
- (5) Follow the specification when stacking packed crates (max. 10).

27.5 SAFETY CAUTIONS

These specifications are intended to preserve the quality assurance of products and individual components.

Before use, check and evaluate the operation when mounted on your products. Abide by these specifications, without deviation when using the products. These products may short-circuit. If electrical shocks, smoke, fire, and/or accidents involving human life are anticipated when a short circuit occurs, then provide the following failsafe functions, as a minimum.

- (1) Ensure the safety of the whole system by installing a protection circuit and a protection device.
- (2) Ensure the safety of the whole system by installing a redundant circuit or another system to prevent a single fault causing an unsafe status.

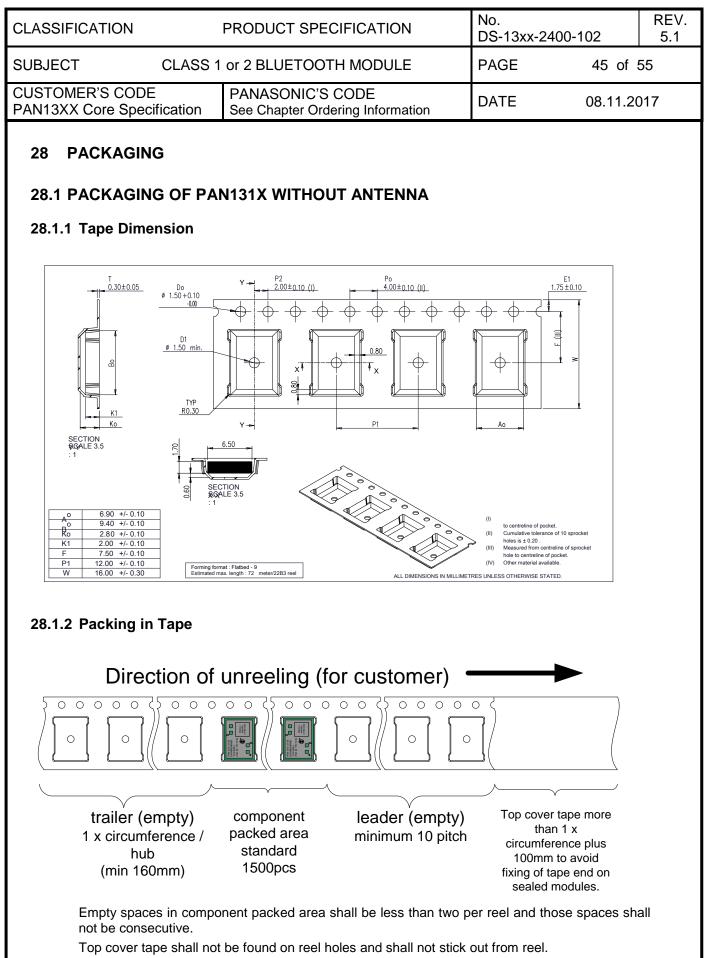
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27.6 OTHER CAUTIONS

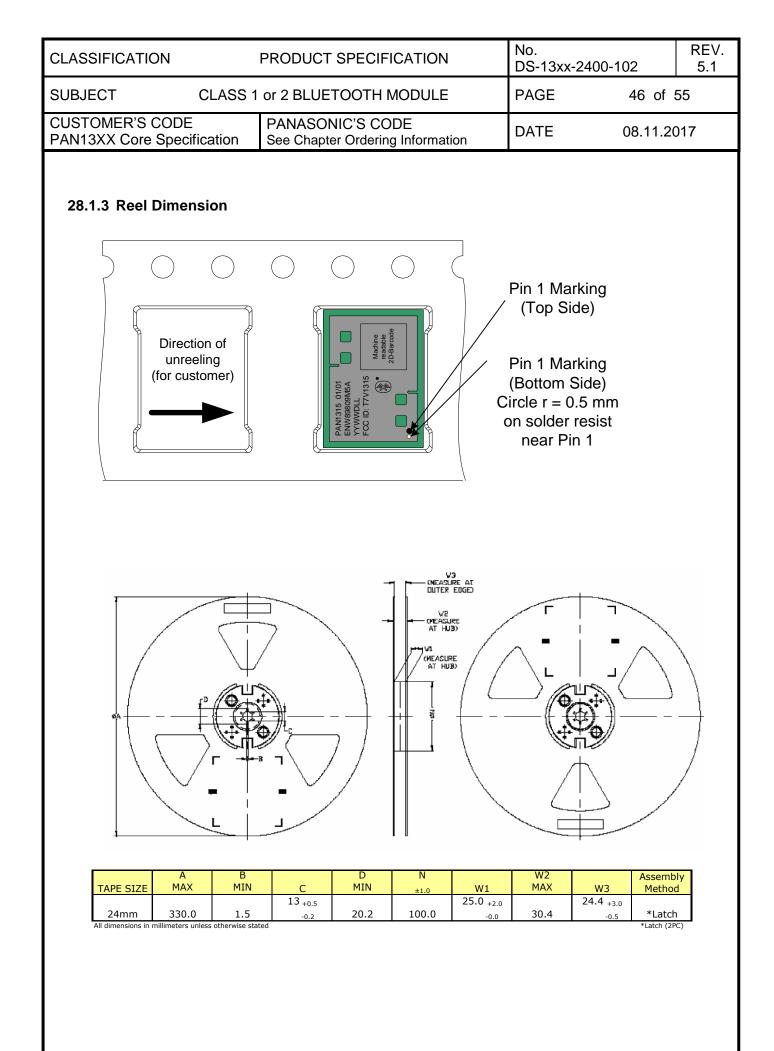
- (1) This specification sheet is copyrighted.
- (2) Do not use the products for other purposes than those listed.
- (3) Be sure to provide an appropriate fail-safe function on your product to prevent an additional damage that may be caused by the abnormal function or the failure of the product.
- (4) This product has been manufactured without any ozone chemical controlled under the Montreal Protocol.
- (5) These products are not intended for other uses, other than under the special conditions shown below. Before using these products under such special conditions, check their performance and reliability under the said special conditions carefully to determine whether or not they can be used in such a manner.
 - In liquid, such as water, salt water, oil, alkali, or organic solvent, or in places where liquid may splash.
 - In direct sunlight, outdoors, or in a dusty environment
 - In an environment where condensation occurs.
 - In an environment with a high concentration of harmful gas (e.g. salty air, HCl, Cl2, SO2, H2S, NH3, and NOX)
- (6) If an abnormal voltage is applied due to a problem occurring in other components or circuits, replace these products with new products because they may not be able to provide normal performance even if their electronic characteristics and appearances appear satisfactory.
- (7) When you have any question or uncertainty, contact Panasonic.

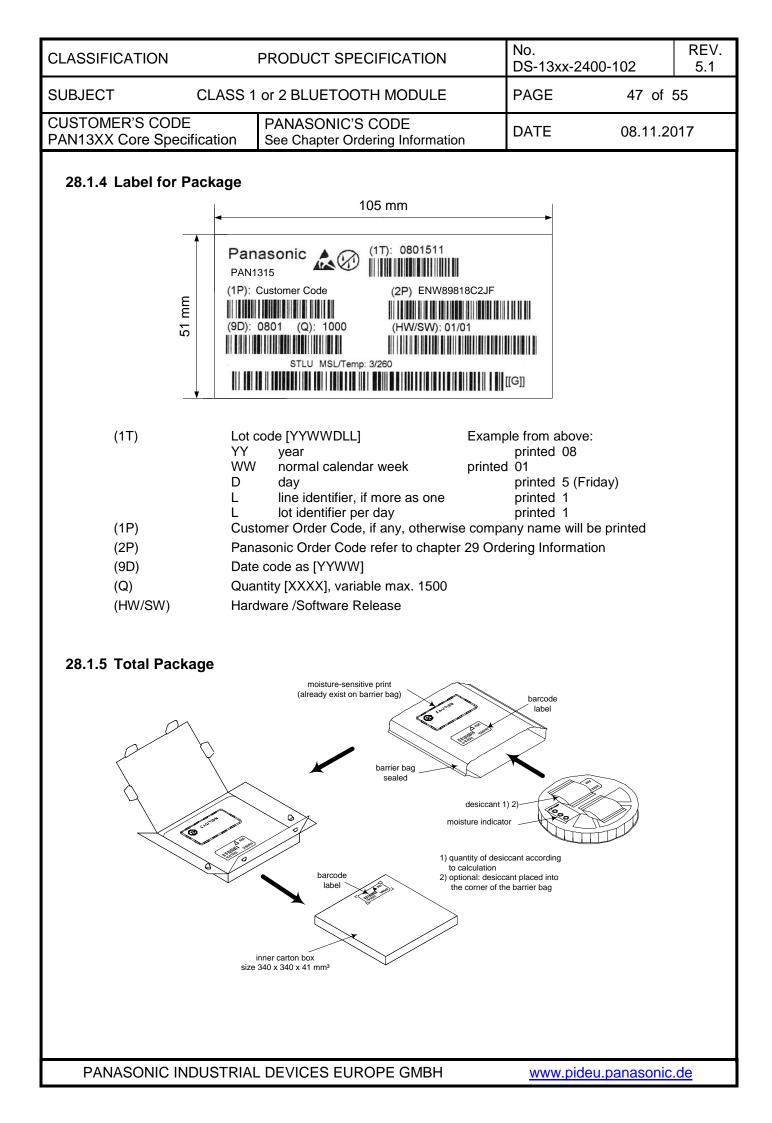
27.7 LIFE SUPPORT POLICY

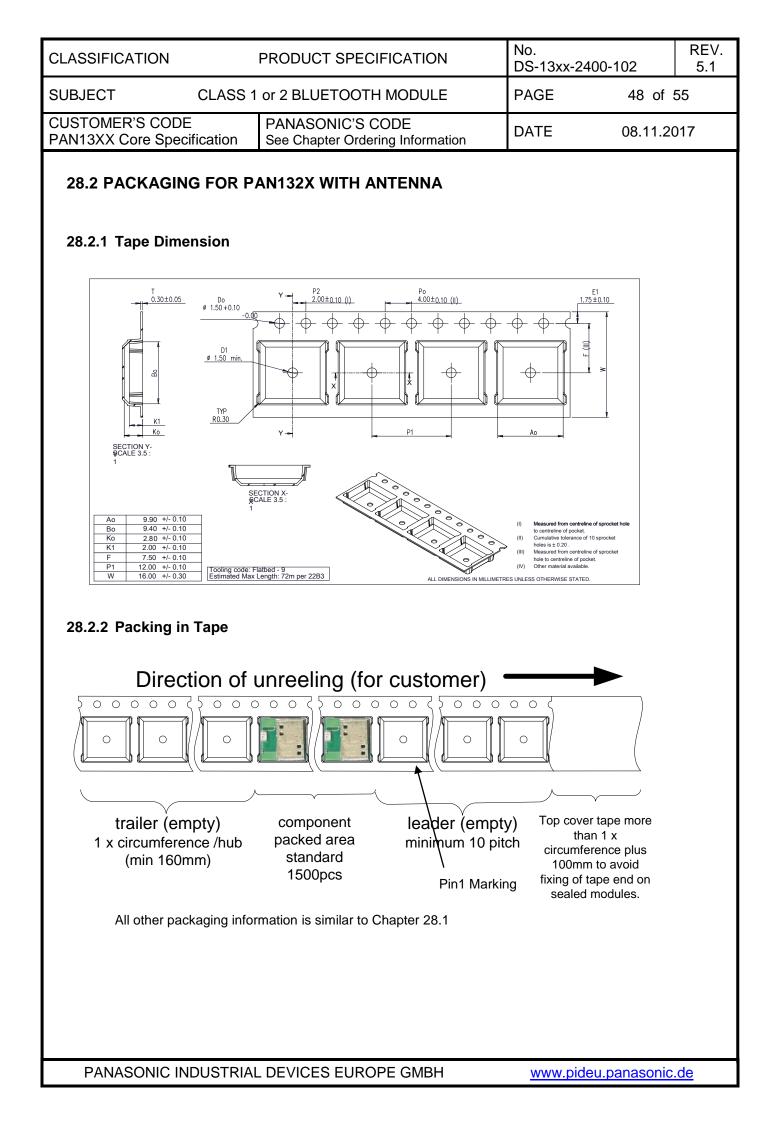
This Panasonic product is not designed for use in life support appliances, devices, or systems where malfunction can reasonably be expected to result in a significant personal injury to the user, or as a critical component in any life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness. Panasonic customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Panasonic for any damages resulting.



Component direction







CLASSIFICATION	PRODUC	CT SPECIFICATIO	N	No. DS-13xx-2400	-102	REV 5.1
SUBJECT	CLASS 1 or 2 BLU	IETOOTH MODUL	E	PAGE	49 of \$	55
CUSTOMER'S COD PAN13XX Core Spe		ONIC'S CODE pter Ordering Informa	ation	DATE	08.11.20)17
29 ORDERING	G INFORMATION					
Model	Temp.	Part Number	TI-Device	Remark		
PAN1315A	-20°C to +70°C	ENW89829C2JF	CC2560A	NR for new dea	signs	
PAN1315A	-40°C to +85°C	ENW89829C2KF	CC2560A	NR for new de	signs	
PAN1315B	-40°C to +85°C	ENW89829C3KF	CC2560B	Recommended	l for new desig	ns
PAN1316	-20°C to +70°C	ENW89823C2JF	CC2564	NR for new dea	signs	
PAN1316	-40°C to +85°C	ENW89823C2KF	CC2564	NR for new de	signs	
PAN1316B	-40°C to +85°C	ENW89823C3KF	CC2564B	Recommended	l for new desig	ns
PAN1317	-20°C to +70°C	ENW89827C2JF	CC2564	NR for new dea	signs	
PAN1317	-40°C to +85°C	ENW89827C2KF	CC2564	NR for new dea	signs	
PAN1323	-20°C to +70°C	ENW89842A2JF	CC2564	NR for new dea	signs	
PAN1323	-40°C to +85°C	ENW89842A2KF	CC2564	NR for new de	signs	
PAN1325A	-20°C to +70°C	ENW89829A2JF	CC2560A	NR for new dea	signs	
PAN1325A	-40°C to +85°C	ENW89829A2KF	CC2560A	NR for new de	signs	
PAN1325B	-40°C to +85°C	ENW89829A3KF	CC2560B	Recommended	l for new desig	ns
PAN1326	-20°C to +70°C	ENW89823A2JF	CC2564	NR for new de	signs	
PAN1326	-40°C to +85°C	ENW89823A2KF	CC2564	NR for new de	signs	
PAN1326B	-40°C to +85°C	ENW89823A3KF	CC2564B	NR for new de	signs	
PAN1327	-20°C to +70°C	ENW89827A2JF	CC2564	NR for new dea	signs	
				1		

NR: Not recommended ETU: Easy to use development board

-40°C to +85°C

30 ROHS DECLARATION

PAN1327

The latest declaration of environmental compatibility (RoHS and REACH) for supplied products can be found on the Panasonic website in the "Downloads" section of the respective product.

ENW89827A2KF

CC2564

NR for new designs

CLASSIFICATION	PRODUCT SPECIFICATION	No. DS-13xx-2400-	·102	REV. 5.1
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31 REGULATORY INFORMATION

31.1 FCC FOR US

31.1.1 FCC Notice



The devices PAN13xx, for details refer to Chapter 28 in this document, including the antennas, which are listed in Chapter 34.1.5 of this data sheet, complies with Part 15 of the FCC Rules. The device meets the requirements for modular transmitter approval as detailed in FCC public Notice DA00-1407.transmitter. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) This device must accept any interference received, including interference that may cause undesired operation.

31.1.2 Caution



The FCC requires the user to be notified that any changes or modifications made to this device that are not expressly approved by Panasonic Industrial Devices Europe GmbH may void the user's authority to operate the equipment.

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help

31.1.3 Labeling Requirements



The Original Equipment Manufacturer (OEM) must ensure that FCC labelling requirements are met. This includes a clearly visible label on the outside of the OEM enclosure specifying the appropriate Panasonic FCC identifier for this product as well as the FCC Notice above. The FCC identifiers are:

FCC ID: T7V1315 for PAN1315 and PAN1325

FCC ID: T7V1316 for PAN1316, PAN1317, PAN1326 and PAN1327

These FCC identifiers are valid for all PAN13xx modules, for details, see the Chapter 29. Ordering Information. In any case the end product must be labelled exterior with "Contains FCC ID: T7V1315" (PAN1315, PAN1325) or

"Contains FCC ID: T7V1316" (PAN1316, PAN1317, PAN1326 and PAN1327).

31.1.4 Antenna Warning



For the related part number of PAN13xx refer to Chapter 29. Ordering Information.

These devices are tested with a standard SMA connector and with the antennas listed below. When integrated in the OEMs product, these fixed antennas require installation preventing endusers from replacing them with non-approved antennas. Any antenna not in the following tables must be tested to comply with FCC Section 15.203 for unique antenna connectors and Section

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15.247 for emissions. The FCC identifier for this device with the antenna listed below are the same (FCC ID: T7V1315 or T7V1316).

31.1.5 Approved Antenna List (PAN1315, PAN1325)

Note: We are able to qualify your antenna and will add to this list as that process is completed.

Item	Part Number	Manufacturer	Frequency Band	Туре	Gain (dBi)
1	2450AT43B100	Johanson Technologies	2.4GHz	Chip-Antenna	+1.3
2	LDA212G3110K	Murata	2.4GHz	Chip-Antenna	+0.9
3	4788930245	Würth Elektronik	2.4GHz	Chip-Antenna	+0.5

31.1.6 Approved Antenna List (PAN1316, PAN1317, PAN1326, PAN1327)

Note: We are able to qualify your antenna and will add to this list as that process is completed.

Item	Part Number	Manufacturer	Frequency Band	Туре	Gain (dBi)
1	LDA212G3110K	Murata	2.4GHz	Chip-Antenna	+0.9
2	ANT2012	Yageo	2.4GHz	Chip-Antenna	+0.9

31.1.7 RF Exposure PAN13xx

To comply with FCC RF Exposure requirements, the Original Equipment Manufacturer (OEM) must ensure that the approved antenna in the previous tables must be installed.

The preceding statement must be included as a CAUTION statement in manuals for products operating with the approved antennas in the previous table to alert users on FCC RF Exposure compliance.

Any notification to the end user of installation or removal instructions about the integrated radio module is not allowed.

The radiated output power of PAN13xx with mounted ceramic antenna (FCC ID: T7V1315 or T7V1316) is far below the FCC radio frequency exposure limits. Nevertheless, the PAN13xx shall be used in such a manner that the potential for human contact during normal operation is minimized.

End users may not be provided with the module installation instructions. OEM integrators and end users must be provided with transmitter operating conditions for satisfying RF exposure compliance.

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31.2 INDUSTRY CANADA CERTIFICATION

31.2.1 IC Notice

This device complies with Industry Canada RSS-210 (Rev.8). Operation is subject to the following two conditions

1) this device may not cause interference, and

2) this device must accept any interference, including interference that may cause undesired operation of the device.

PAN131x is licensed to meet the regulatory requirements of Industry Canada (IC), license: IC: 216Q-1315 (PAN1315, PAN1325)

IC: 216Q-1316 (PAN1316, PAN1317, PAN1326, PAN1327)

Manufacturers of mobile, fixed or portable devices incorporating this module are advised to clarify any regulatory questions and ensure compliance for SAR and/or RF exposure limits. Users can obtain Canadian information on RF exposure and compliance from <u>www.ic.gc.ca</u>.

This device has been designed to operate with the antennas listed in Tables 31.1.5 and 31.1.6 above, having a maximum gain of 1.3 dBi (PAN13x6: 0.9dBi). Antennas not included in this list or having a gain greater than 1.3 dBi (PAN13x6: 0.9dBi) are strictly prohibited for use with this device. The required antenna impedance is 50 ohms. The antenna used for this transmitter must not be co-located or operating in conjunction with any other antenna or transmitter. Due to the model size the IC identifier is displayed in the installation instruction.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes :

(1) l'appareil ne doit pas produire de brouillage, et

(2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

PAN131x est garanti conforme aux dispositions règlementaires d'Industry Canada (IC), licences: IC: 216Q-1315 (PAN1315, PAN1325)

IC: 216Q-1316 (PAN1316, PAN1317, PAN1326, PAN1327)

Il est recommandé aux fabricants d'appareils fixes, mobiles ou portables de consulter la réglementation en vigueur et de vérifier la conformité de leurs produits relativement aux limites d'exposition aux rayonnements radiofréquence ainsi qu'au débit d'absorption spécifique maximum autorisé.

Des informations pour les utilisateurs sur la réglementation Canadienne concernant l'exposition aux rayonnements RF sont disponibles sur le site <u>www.ic.gc.ca</u>.

Ce produit a été développé pour fonctionner spécifiquement avec les antennes listées dans le tableau ci-dessus, présentant un gain maximum de 1.3dBi (PAN13x6:0.9dBi). Des antennes autres que celles listées ici, ou présentant un gain supérieur à 1.3dBi (PAN13x6: 0.9dBi) ne doivent en aucune circonstance être utilises en combinaison avec ce produit. L'impédance des antennes compatibles est 500hm. L'antenne utilisée avec ce produit ne doit ni être située à proximité d'une autre antenne ou d'un autre émetteur, ni être utilisée conjointement avec une autre antenne ou un autre émetteur. En raison de la taille du produit, l'identifiant IC est fourni dans le manuel d'installation.

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31.2.2	This includes a clearly appropriate Panasonic identifiers are: IC: 216Q-1315 (PAN131 IC: 216Q-1316 (PAN131 These IC identifiers are Information. In any "Contains IC: 216Q-131 "Contains IC: 216Q-131 Obligations d'étiquetag Les fabricants d'équipen produit final sont remplie de l'emballage externe, o notification ci-dessus. Les identifiants IC sont: IC: 216Q-1315 (PAN131 IC: 216Q-1316 (PAN131 Ces identifiants sont vali Dans tous les cas les pro- mentions suivantes: "Contient IC: 216Q-1315	Manufacturer (OEM) must ensure that IC visible label on the outside of the O IC identifier for this product as well as 5, PAN1325) 6, PAN1317, PAN1326, PAN1327) valid for all PAN13xx modules, for details case the end product must 5 " (PAN1315, PAN1325) or 6 " (PAN1316, PAN1317, PAN1326 and P ge nents (OEM) doivent s'assurer que les oblise. Ces obligations incluent une étiquette of comportant l'identifiant IC du module Pana	EM enclosure specifying the IC Notice above. The see the Chapter 29. Order be labelled exterior AN1327). igations d'étiquetage du lairement visible à l'extérieur asonic inclus, ainsi que la pter 29. Ordering Information pallage externe une des	the e IC ring with

CLASSIFICATION		PRODUCT SPECIFICATION	No. DS-13xx-2400)-102	REV. 5.1
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31.3 EUROPEAN COM	IFO	RMITY ACCORDING TO RED (20	14/53/EU)		

All modules described in this Product Specification comply with the standards according to the following LVD (2014/35/EU), EMC-D (2014/30/EU) together with the RED (2014/53/EU) articles:

3.1a Safety/Health: EN60950-1:2006+A11:2009+A1:2010+A12:2011+AC:2011+A2:2013 EN62311:2008

- 3.1b EMC: EN 301 489-1 V2.1.1:2017-02 EN 301 489-17 V3.1.1:2017-02
- 3.2 Radio: EN 300 328 V2.1.1:2016-11

As a result of the conformity assessment procedure described in the 2014/53/EU Directive, the end customer equipment should be labelled as follows:

CE

PAN13xx and its model versions in the specified reference design can be used in all countries of the European Economic Area (Member States of the EU, European Free Trade Association States [Iceland, Liechtenstein, Norway]), Monaco, San Marino, Andorra, and Turkey.

CLASSIFICATION	F	PRODUCT SPECIFICATION	No. DS-13xx-2	400-102 K
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31.4 JAPANESE R BUSINESS L	-	AW AND JAPANESE TELEC IPLIANCE	OMMUNICATIO	ONS
This device become invalid	should no	rsuant to the Japanese Radio Law (ot be modified (otherwise the qualified for the Japanese market:		ion number will
ENW89823A2I		MIC ID: [R]202-LSD072		
ENW89823A3I	KF	MIC ID: [R]202-LSD072		
ENW89829A2I	KF	MIC ID: [R]202-LSD073		
ENW89829A3I	ΚF	MIC ID: [R]202-LSD073		
This device sh invalid). 1. Indicate the equipment can	nould not e following be crosse	rsuant to the Korean Law. be modified (otherwise the grante expression on the product where d during operation." o中で電波混信可能性がある"という	e it can be easily a	seen: "This radio
示すること =>	"該当の無	線設備は運用の中で電波混信可能性	主がある "	
		installer should fully inform the ope relevant to the human life safety, as		
製作者及び設置 出	量者は当該の	の無線設備が電波混信可能性がある	ので人命安全と係	わるサービスは
来ないことをマ	マニュアル	などを通じて運用者及び使用者に充	ご分に知らせること	
=> "該当の無線	設備が電源	皮混信可能性がありますので人命安	全と係わるサービン	スは出来ません"
The MSIP num This ID is valid ENW89823A3I	for:	IP-CRM-Pid-ENW89823A3KF		
31.6 BLUETOOTH	SIG ST	ATEMENT		

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Bluetooth Development Tools - 802.15.1 category:

Click to view products by Panasonic manufacturer:

Other Similar products are found below :

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